LAMPIRAN

Lampiran A

Kata - kata yang direkam dan diputar kembali pada ISD 2560 yaitu :

1. Nol
2. Satu
3. Dua
4. Tiga
5. Empat
6. Lima
7. Enam
8. Tujuh
9. Delapan
10. Sembilan
11. Alat ukur tinggi badan manusia *Portable*
12. Tinggi badan anda
13. Error
14. Centimeter
15. Kurang tinggi

LAMPIRAN B

LISTING PROGRAM BAHASA ASSEMBLY

```
;----- Dewi Sutanti Karyadi 5103003002 -----
 ;p0   Data lcd
 ;p2.0 RS
 ;p2.1 R/W
 ;p2.2 E
 ;p1.0 CE
 ;p1.1 PD
 ;p1.2 EOM
 ;p1.3 M0
 ;p2.6 Ref saklar
 ;p2.7 Input saklar
 ;p3.0 Input sensor
 ;p3.2 Select sensor 1
 ;p3.3 Select sensor 2

org 0h
 ;----- Penyimpanan Data 30H-7FH -----

 ;----- delay -----
 ;---15ms---
 delay1 equ 30h
 delay2 equ 31h
 ;---15ms end---

 ;---isd---
 delayisd_1 equ 33h
 delayisd_2 equ 34h
 ;---isd end---
 ;----- delay end -----

 ;----- data sensor -----
 ;----- data sensor 1 -----
 sens_1_a equ 40h
 sens_1_b equ 41h
 sens_1_c equ 42h
 hasil_ukur_sens1 equ 43h
 sens_1_2_a equ 50h
 sens_1_2_b equ 51h
 sens_1_2_c equ 52h
 ;----- data sensor 1 end -----
 ;----- data sensor 2 -----
 sens_2_a equ 44h
 sens_2_b equ 45h
 sens_2_c equ 46h
 hasil_ukur_sens2 equ 47h
 sens_2_2_a equ 55h
 sens_2_2_b equ 56h
 sens_2_2_c equ 57h
 ;----- data sensor 2 end -----
```

```
hasil_pengurangan equ 4ah
inch_cm equ 4bh
final_a equ 4ch
final_b equ 4dh
final_c equ 4eh
;----- data sensor end -----
;----- data ISD -----
ce equ p1.0
pd equ p1.1
eom equ p1.2
m0 equ p1.3
lewat equ 70h
;----- data ISD end -----
;----- Penyimpanan Data 30H-7FH end -----

;------ Init LCD -------
mov a,#38h
acall init_lcd
acall delay
mov a,#0ch
acall init_lcd
acall delay
mov a,#01h
acall init_lcd
acall delay
mov a,#06h
acall init_lcd
acall delay
;------ Init LCD end ------

;------ Program utama ------
mulai:
clr m0          ;nonaktifkan M0
setb ce         ;mengkondisikan CE agar standby
clr pd          ;reset ISD
clr p3.3        ;mematikan sensor 2
clr p2.6        ;referensi tombol start
setb p2.7       ;mengkondisikan tombol start menjadi High
acall tulis_intro      ;menampilkan intro pada LCD
acall intro     ;menampilkan intro pada ISD

ulang_dr_error:
acall tulis_tombol_start ;menampilkan "Tekan..." pada LCD

tunggu_start:
jb p2.7,tunggu_start   ;tunggu tombol start di tekan
jmp sensor      ;mengukur sensor ketika tombol start ditekan

lanjutan_stlh_ada_hsl:
acall tulis_tinggi_anda ;menulis "Tinggi anda..." pada LCD
mov a,#0c9h
acall init_lcd
acall delay
acall hasil_ke_lcd     ;menulis hasil pengukuran tinggi ke LCD
acall tulis_cm         ;menulis "cm" pd LCD
acall tinggi_bdn_anda  ;menampilkan "Tinggi bdn..." pd ISD
```

```
acall hasil_ke_isd      ;menampilkan hasil pengukuran pd ISD
acall sentimeter        ;menampilkan "Sentimeter" pd ISD
jmp ulang_dr_error
;------ Program utama end ------

;----- Sensor -----
sensor:
mov tmod,#20h     ;timer 1 mode 2
mov th1,#-3       ;baud rate 9600bps
mov scon,#50h     ;8 bit,1 stop bit
setb tr1
setb p3.2         ;aktifkan sensor 1
clr p3.3          ;nonaktifkan sensor 2
acall delay
;acall delay

data_sensor1:
clr ri
jnb ri,$
mov a,sbuf
cjne a,#'R',data_sensor1 ;deteksi huruf "R"
clr ri
jnb ri,$
mov sens_1_a,sbuf       ;mengambil angka pertama
clr ri
jnb ri,$
mov sens_1_b,sbuf       ;mengambil angka kedua
clr ri
jnb ri,$
mov sens_1_c,sbuf       ;mengambil angka ketiga
clr ri

;----- Tambahan sensor 1 -----
tunggu_sensor1_2:
clr ri
jnb ri,$
mov a,sbuf
cjne a,#'R',tunggu_sensor1_2        ;deteksi huruf "R"
clr ri
jnb ri,$
mov sens_1_2_a,sbuf           ;mengambil angka pertama
clr ri
jnb ri,$
mov sens_1_2_b,sbuf           ;mengambil angka kedua
clr ri
jnb ri,$
mov sens_1_2_c,sbuf           ;mengambil angka ketiga
clr ri
;----- Tambahan sensor 1 end -----

;ascii_to_hex_sens1
anl sens_1_a,#0fh       ;mengubah angka ke1 menjadi heksa
mov a,sens_1_a
mov b,#100
mul ab                  ;mengubah angka ke1 menjadi ratusan
mov sens_1_a,a
```

```
anl sens_1_b,#0fh       ;mengubah angka ke2 menjadi heksa
mov a,sens_1_b
mov b,#10               ;mengubah angka ke2 menjadi puluhan
mul ab
mov sens_1_b,a
anl sens_1_c,#0fh       ;mengubah angka ke3 menjadi heksa
mov a,sens_1_a
add a,sens_1_b
add a,sens_1_c          ;menjumlah ratusan, puluhan, dan satuan
mov hasil_ukur_sens1,a

;ascii_to_hex_sens1_2
anl sens_1_2_a,#0fh     ;mengubah angka ke1 menjadi heksa
mov a,sens_1_2_a
mov b,#100
mul ab                  ;mengubah angka ke1 menjadi ratusan
mov sens_1_2_a,a
anl sens_1_2_b,#0fh     ;mengubah angka ke2 menjadi heksa
mov a,sens_1_2_b
mov b,#10
mul ab                  ;mengubah angka ke2 menjadi puluhan
mov sens_1_2_b,a
anl sens_1_2_c,#0fh     ;mengubah angka ke3 menjadi heksa
mov a,sens_1_2_a
add a,sens_1_2_b
add a,sens_1_2_c        ;menjumlah ratusan, puluhan, dan satuan
cjne a,hasil_ukur_sens1,ke_data_sensor1
jmp lanjut_data_sensor1      ;menunggu data sampai stabil

ke_data_sensor1:
jmp data_sensor1
lanjut_data_sensor1:
cjne a,#7,sens1_hex_ulang  ;jarak min sensor diatas kepala 17,5cm
sens1_hex_ulang:
jnc cek_30
acall tulis_kurang_dr_15cm
acall kurang_dr_15cm
jmp ulang_dr_error

cek_30:
cjne a,#30,sens1_hex_ulang_2 ;jarak sensor diatas kepala <75cm
sens1_hex_ulang_2:
jc simpan_sens1
acall tulis_error
acall error
jmp ulang_dr_error
simpan_sens1:
mov hasil_ukur_sens1,a
setb p3.3               ;mengaktifkan sensor 2
clr p3.2                ;mematikan sensor 1
acall delay
;acall delay

data_sensor2:
clr ri
jnb ri,$
```

```
mov a,sbuf
cjne a,#'R',data_sensor2
clr ri
jnb ri,$
mov sens_2_a,sbuf
clr ri
jnb ri,$
mov sens_2_b,sbuf
clr ri
jnb ri,$
mov sens_2_c,sbuf
clr ri
```

Pengambilan data ke1 Sensor 2

```
;----- Tambahan sensor 2 -----
data_sensor2_2:
clr ri
jnb ri,$
mov a,sbuf
cjne a,#'R',data_sensor2_2
clr ri
jnb ri,$
mov sens_2_2_a,sbuf
clr ri
jnb ri,$
mov sens_2_2_b,sbuf
clr ri
jnb ri,$
mov sens_2_2_c,sbuf
clr ri
;----- Tambahan sensor 2 end -----

clr p3.3
setb p3.2
;ascii_to_hex_sens2
anl sens_2_a,#0fh
mov a,sens_2_a
mov b,#100
mul ab
mov sens_2_a,a
anl sens_2_b,#0fh
mov a,sens_2_b
mov b,#10
mul ab
mov sens_2_b,a
anl sens_2_c,#0fh
mov a,sens_2_a
add a,sens_2_b
add a,sens_2_c
mov hasil_ukur_sens2,a
;ascii_to_hex_sens2_2
anl sens_2_2_a,#0fh
mov a,sens_2_2_a
mov b,#100
mul ab
mov sens_2_2_a,a
anl sens_2_2_b,#0fh
```

Pengambilan data ke2 Sensor 2

```
mov a,sens_2_2_b
mov b,#10
mul ab
mov sens_2_2_b,a
anl sens_2_2_c,#0fh
mov a,sens_2_2_a
add a,sens_2_2_b
add a,sens_2_2_c

cjne a,hasil_ukur_sens2,ke_data_sensor2 ;menunggu data stabil
jmp lanjut_data_sensor2
ke_data_sensor2:
jmp data_sensor2
lanjut_data_sensor2:
cjne a,hasil_ukur_sens1,sens2_hex_ulang ;jika sens1=sens2, error
sens2_hex_ulang:
jnc lanjut_proses
acall tulis_error
acall error
jmp ulang_dr_error
lanjut_proses:
mov a,hasil_ukur_sens2
cjne a,#120,lanjut_proses_lg        ;jarak maksimum 300cm
lanjut_proses_lg:
jc lanjut_proses_sekali_lg
acall tulis_error
acall error
jmp ulang_dr_error
lanjut_proses_sekali_lg:

mov a,hasil_ukur_sens2
subb a,hasil_ukur_sens1      ;jarak sens2 - jarak sens1
mov hasil_pengurangan,a
cjne a,#20,lanjut_proses2    ;jarak minimum 50cm
lanjut_proses2:
jnc sensor_beres
acall tulis_error
acall error
jmp ulang_dr_error

sensor_beres:

;inch_to_cm
mov b,#2
mul ab
mov inch_cm,a
mov a,hasil_pengurangan
mov b,#2
div ab
add a,inch_cm
mov hasil_pengurangan,a

;hex_to_bcd
mov a,hasil_pengurangan
mov b,#100
div ab
```

Inci ke Cm

```
mov final_a,a
mov a,hasil_pengurangan
mov b,#10
div ab
mov b,#10
div ab
mov final_b,b
mov a,hasil_pengurangan
mov b,#10
div ab
mov final_c,b
jmp lanjutan_stlh_ada_hsl
;----- Sensor end -----

;----- Tampilkan hasil ke lcd -----
hasil_ke_lcd:
mov a,final_a
cjne a,#0h,hasil_ke_lcd_lanjut1
jmp hasil_ke_lcd_2
hasil_ke_lcd_lanjut1:
add a,#30h
acall write_lcd
acall delay
jmp hasil_ke_lcd_lanjut2
hasil_ke_lcd_2:
mov a,final_b
cjne a,#0h,hasil_ke_lcd_lanjut2
jmp hasil_ke_lcd_3
hasil_ke_lcd_lanjut2:
mov a,final_b
add a,#30h
acall write_lcd
acall delay
hasil_ke_lcd_3:
mov a,final_c
add a,#30h
acall write_lcd
acall delay
ret
;----- Tampilkan hasil ke lcd end -----

;----- Tampilkan hasil ke isd -----
hasil_ke_isd:
mov a,final_a
cjne a,#0h,hasil_ke_isd_lanjut1
jmp hasil2_ke_isd
hasil_ke_isd_lanjut1:
mov lewat,a
acall play
jmp hasil_ke_isd_lanjut2
hasil2_ke_isd:
mov a,final_b
cjne a,#0h,hasil_ke_isd_lanjut2
jmp hasil3_ke_isd
hasil_ke_isd_lanjut2:
mov lewat,final_b
```

Heksa ke BCD

Hasil ke LCD

Hasil ke ISD

```
acall play
hasil3_ke_isd:
mov a,final_c
mov lewat,a
acall play
ret
;----- Tampilkan hasil ke isd end -----

;------- LCD -------
tulis_intro:
acall clr_lcd
mov a,#081h
acall init_lcd
acall delay
mov dptr,#intro_baris1
acall tulis
mov a,#0c3h
acall init_lcd
acall delay
mov dptr,#intro_baris2
acall tulis
ret

tulis_tombol_start:
acall clr_lcd
mov a,#082h
acall init_lcd
acall delay
mov dptr,#tombol_start_baris1
acall tulis
mov a,#0c4h
acall init_lcd
acall delay
mov dptr,#tombol_start_baris2
acall tulis
ret

tulis_mengukur:
acall clr_lcd
mov a,#082h
acall init_lcd
acall delay
mov dptr,#mengukur
acall tulis
ret
tulis_error:
acall clr_lcd
mov a,#084h
acall init_lcd
acall delay
mov dptr,#lcd_error
acall tulis
ret
tulis_kurang_dr_15cm:
acall clr_lcd
mov a,#082h
```

```
acall init_lcd
acall delay
mov dptr,#lcd_kurang_dr_15cm_baris1
acall tulis
mov a,#0c4h
acall init_lcd
acall delay
mov dptr,#lcd_kurang_dr_15cm_baris2
acall tulis
ret

tulis_tinggi_anda:
acall clr_lcd
mov a,#082h
acall init_lcd
acall delay
mov dptr,#tinggi_anda_baris1
acall tulis
mov a,#0c0h
acall init_lcd
acall delay
mov dptr,#tinggi_anda_baris2
acall tulis
ret

tulis_cm:
mov dptr,#tinggi_anda_baris2_2
acall tulis
ret
clr_lcd:
mov a,#01
acall init_lcd
acall delay
ret

tulis:
ulang_tulis:
clr a
movc a,@a+dptr
acall write_lcd
acall delay
inc dptr
jz selesai_tulis
sjmp ulang_tulis
selesai_tulis:
ret

init_lcd:
mov p0,a
clr p2.0
clr p2.1
setb p2.2
acall delay
clr p2.2
ret
```

LAMPIRAN C

PETUNJUK PENGGUNAAN

ALAT UKUR TINGGI BADAN MANUSIA PORTABEL

1. Hidupkan alat dengan menekan tombol 1 untuk ON/OFF.

2. Letakkan alat diatas kepala dengan tangan kedua seperti terlihat pada gambar dibawah dengan jarak antara 15 Cm – 50 Cm dari atas kepala.

3. Tekan tombol 2 untuk memulai pengukuran.

   Ada beberapa kemungkinan yang akan terjadi :

   - Apabila kedua sensor dapat menerima signal yang dipantulkan dari obyek dengan baik maka hasil dari pengukuran tinggi badan akan langsung tampil pada LCD dan terdengar lewat speaker.
   - Apabila jarak yang diukur kedua sensor tidak sesuai maka akan tampil pada LCD dan terdengar pada speaker "error" dan "kurang tinggi".

4. Selesai matikan alat dengan menekan tombol 1 untuk ON/OFF.

Catatan :

Terjadi error atau kurang tinggi ada beberapa kemungkian seperti :
"Error"

- Jarak yang diukur kedua sensor sama
- Posisi sensor tidak tepat mengenai objek yang akan diukur.
- Hasil ukuran tinggi badan kurang dari 50 Cm atau lebih dari 300 Cm.

"Kurang tinggi"

- Jarak sensor 1 ke kepala kurang dari 15 Cm – 50 Cm

BIODATA PENULIS

Nama : Dewi Sutanti Karyadi

NRP : 5103003002

Tempat, tanggal lahir : Makassar, 18 Oktober 1984

Agama : Katolik

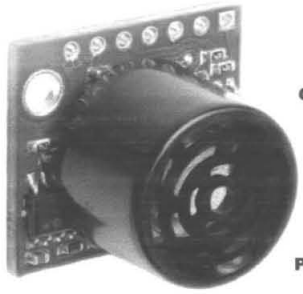
Alamat : Klampis Semolo Timur AB 52 Surabaya

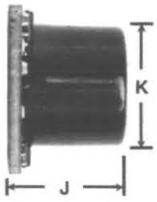
Riwayat Pendidikan :

- Tahun 1991, Lulus SD Katolik ST Fransiskus Xaverius. Palu, Sulawesi Tengah.
- Tahun 1997, Lulus SLTP Katolik ST. Paulus Palu, Sulawesi Tengah.
- Tahun 2003, Lulus SMU Katolik ST. Hendrikus Surabaya, Jawa Timur.
- Tahun 2003 hingga buku ini ditulis, tercatat sebagai mahasiswa di Jurusan Teknik Elektro, Fakultas Teknik, Universitas Katolik Widya Mandala, Surabaya.

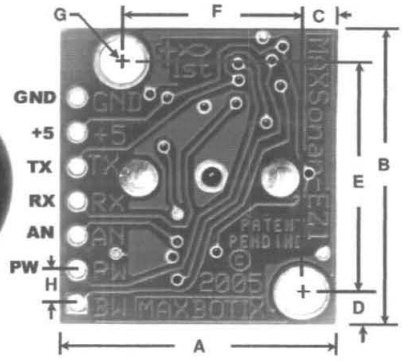
The MaxSonar®-EZ1™ High Performance Sonar Range Finder

The MaxSonar®-EZ1™ offers very short to long-range detection and ranging, in an incredibly small package with ultra low power consumption. The MaxSonar®-EZ1™ detects objects from 0-inches to 254-inches (6.45-meters) and provides sonar range information from 6-inches out to 254-inches with 1-inch resolution. Objects from 0-inches to 6-inches range as 6-inches. The interface output formats included are pulse width output, analog voltage output, and serial digital output.





approximately actual size



weight, 4.3 grams

A	0.785"	19.9 mm	F	0.510"	12.6 mm
B	0.870"	22.1 mm	G	0.124" dia.	3.1 mm dia.
C	0.100"	2.54 mm	H	0.100"	2.54 mm
D	0.100"	2.54 mm	J	0.645"	16.4 mm
E	0.670"	17.0 mm	K	0.610"	15.5 mm

dimensions are nominal

Features

- Continuously variable gain for beam control and side lobe suppression
- Object detection includes zero range objects
- Single 5V supply with 2mA typical current draw
- Readings can occur up to every 50mS, (20-Hz rate)
- Free run operation can continually measure and output range information
- Triggered operation provides the range reading as desired
- All interfaces are active simultaneously
  - Serial, 0 to 5V
    - 9600Baud, 81N
  - Analog (10mV/inch)
  - Pulse width (147uS/inch)
- Learns ringdown pattern when commanded to start ranging
- Designed for protected indoor environments
- Sensor operates at 42KHz
- High output 10V PP square wave sensor drive

Benefits

- Very low cost sonar ranger
- Half the size of other sensors in its class
- Sensor dead zone virtually gone
- No central blind spot
- Quality beam characteristics
- Mounting holes provided on the circuit board
- Lowest power ranger, excellent for multiple sensor or battery based systems
- Can be triggered externally or internally
- Sensor reports the range reading directly, frees up user processor
- Fast measurement cycle
- User can choose any of the three sensor outputs

Beam Characteristics

Sample results for measured beam patterns are shown below on a 12-inch grid. The detection pattern is shown for;

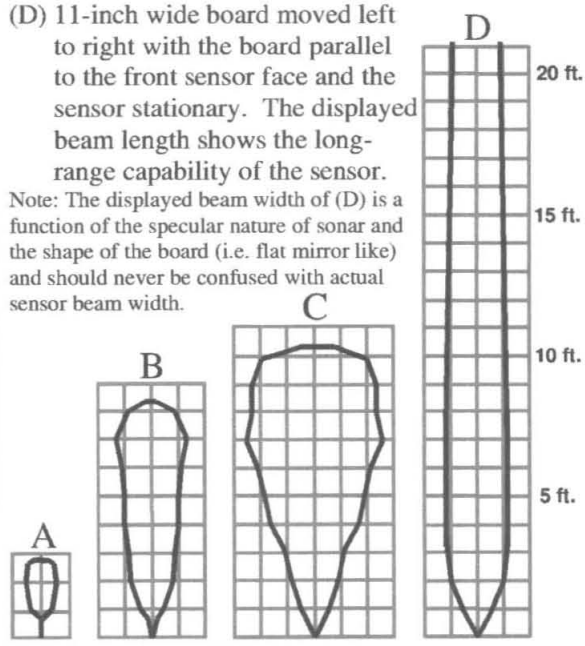
(A) 0.25-inch diameter dowel, note the very narrow beam for close small objects,

(B) 1-inch diameter dowel, dowel, note the long narrow detection pattern,

(C) 3.25-inch diameter rod, note the long controlled detection pattern,

(D) 11-inch wide board moved left to right with the board parallel to the front sensor face and the sensor stationary. The displayed beam length shows the long-range capability of the sensor.

Note: The displayed beam width of (D) is a function of the specular nature of sonar and the shape of the board (i.e. flat mirror like) and should never be confused with actual sensor beam width.



beam characteristics are approximate

MaxBotix® Inc.

8757 East Chimney Spring Drive, Tucson AZ, 85747 USA
1821 Graydon Avenue, Brainerd, MN, 56401 USA
Email: info@maxbotix.com Web:www.maxbotix.com

```
write_lcd:
mov p0,a
setb p2.0
clr p2.1
setb p2.2
acall delay
clr p2.2
ret
;------- LCD end -------

;-------- ISD --------
intro:
mov lewat,#0ah
acall play
ret

error:
mov lewat,#0bh
acall play
ret

sentimeter:
mov lewat,#0ch
acall play
ret

tinggi_bdn_anda:
mov lewat,#0dh
acall play
ret

kurang_dr_15cm:
mov lewat,#0eh
acall play
ret

play:
setb pd
acall delay_isd
clr pd
acall delay_isd
mov a,lewat
cjne a,#0h,lanjut_kurangi
jmp mainkan
lanjut_kurangi:
setb m0
acall delay_isd
lanjut_kurangi2:
clr ce
acall delay_isd
setb ce
acall delay_isd
dec a
cjne a,#0h,lanjut_kurangi2
```

```
mainkan:
clr m0
acall delay_isd
clr ce
acall delay_isd
setb ce

tunggu_play:
jb eom,tunggu_play
ret
;---------- ISD End ---------

;----- delay -----
delay:
mov delay1,#75
ulang_delay:
mov delay2,#200
djnz delay2,$
djnz delay1,ulang_delay
ret
;----- delay end -----

;----- delay isd -----
delay_isd:
mov delayisd_1,#75
ulang_delay_isd:
mov delayisd_2,#100
djnz delayisd_2,$
djnz delayisd_1,ulang_delay_isd
ret
;----- delay isd end -----

;------- Data LCD -------
org 400h
intro_baris1: db "Dewi Sutanti K ",0
intro_baris2: db "5103003002    ",0
tombol_start_baris1: db "Tekan tombol  ",0
tombol_start_baris2: db "Start...     ",0
mengukur: db "Mengukur...    ",0
lcd_error: db "Error !!     ",0
lcd_kurang_dr_15cm_baris1: db "Kurang dari    ",0
lcd_kurang_dr_15cm_baris2: db "15 Cm !      ",0
tinggi_anda_baris1: db "Tinggi anda    ",0
tinggi_anda_baris2: db "  adalah          ",0
tinggi_anda_baris2_2: db " Cm      ",0
;------- Data LCD end ------

end
```

MaxSonar®-EZ1™ Pin Out

GND – Return for the DC power supply. Must be ripple and noise free for best operation.

+5V – Requires 5VDC +/- 0.5VDC. Current capability of 3mA capacity recommended.

TX – Delivers asynchronous serial with an RS232 format, except voltages are 0-5V. The output is an ASCII capital "R", followed by three ASCII character digits representing the range in inches up to a maximum of 255, followed by a carriage return (ASCII 13). The baud rate is 9600, 8 bits, no parity, with one stop bit. Although the voltage of 0-5 V is outside the RS232 standard, most RS232 devices have sufficient margin to read 0-5V serial data. If standard voltage level RS232 is desired, invert, and connect an RS232 converter such as a MAX232.

RX – This pin is internally pulled high. The EZ1™ will continually measure range and output if RX data is left unconnected or held high. If held low the EZ1™ will stop ranging. Bring high for 20uS or more to command a range reading.

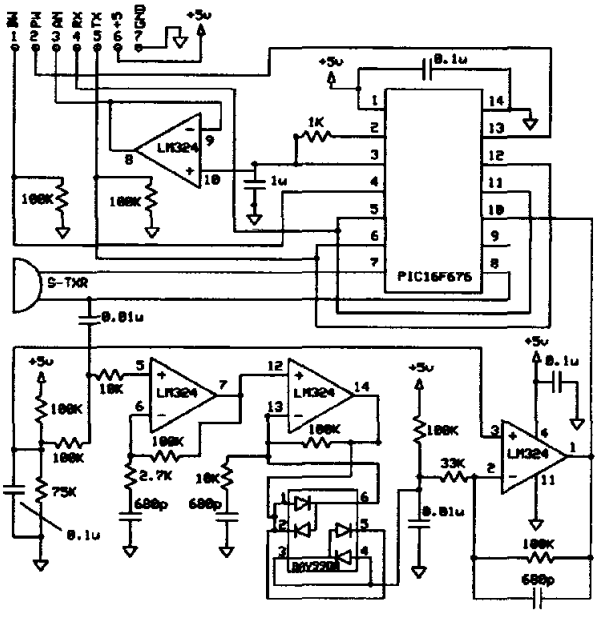
AN – Outputs 0 to 2.55 volts with a scaling factor of 10mV per inch. The output is buffered and corresponds to the most recent range data.

PW – This pin outputs a pulse width representation of range. The distance can be calculated using the scale factor of 147uS per inch.

BW – N.C., Reserved

MaxSonar®-EZ1™ Circuit

The MaxSonar®-EZ1™ sensor functions using active components consisting of an LM324, a diode array, a PIC16F676, together with a variety of passive components.



MaxSonar®-EZ1™ Timing Description

250mS after power-up, the MaxSonar®-EZ1™ is ready to accept the RX command. If the RX pin is left open or held high, the sensor will first run a calibration cycle (49mS), and then it will take a range reading (49mS). Therefore, the first reading will take 100mS. Subsequent readings will take 49mS. The MaxSonar®-EZ1™ checks the RX pin at the end of every cycle. Range data can be acquired once every 49mS.

Each 49mS period starts by the RX being high or open, after which the MaxSonar®-EZ1™ sends seven 42KHz waves, after which the pulse width pin (PW) is set high. When a target is detected the PW pin is pulled low. The PW pin is high for up to 37.5mS if no target is detected. During the next 4.7mS the serial data is sent. The remainder of the 49mS time is spent adjusting the analog voltage to the correct level. When a long distance is measured immediately after a short distance reading, the analog voltage may not reach the exact level within one read cycle. The MaxSonar®-EZ1™ timing is factory calibrated to one percent and in use is better than two percent.

MaxSonar®-EZ1™ General Power-Up Instruction

Each time after the MaxSonar®-EZ1™ is powered up, it will calibrate during its first read cycle. The sensor uses this stored information to range a close object. It is important that objects not be close to the sensor during this calibration reading. The best sensitivity is obtained when it is clear for fourteen inches, but good results are common when clear for at least seven inches. If an object is too close during the calibration cycle, the sensor may then ignore objects at that distance.

The MaxSonar®-EZ1™ does not use the calibration data to temperature compensate for range, but instead to compensate for the sensor ringdown pattern. If the temperature, humidity, or applied voltage changes during operation, the sensor may require recalibration to reacquire the ringdown pattern. If the temperature increases, the sensor is more likely to have false close readings. If the temperature decreases, the sensor is more likely to have reduced up close sensitivity. To recalibrate the MaxSonar®-EZ1™, cycle power, then command a read cycle.

MaxBotix® Inc.
MaxBotix, MaxSonar & EZ1 are trademarks of MaxBotix Inc.
EZ1™ • v1.0 • 10/2006 patent pending

8757 East Chimney Spring Drive, Tucson AZ, 85747 USA
1821 Graydon Avenue, Brainerd, MN, 56401 USA
Email: info@maxbotix.com Web:www.maxbotix.com

Winbond Electronics Corp.

ISD2560/75/90/120

SINGLE-CHIP, MULTIPLE-MESSAGES,

VOICE RECORD/PLAYBACK DEVICE

60-, 75-, 90-, AND 120-SECOND DURATION

Publication Release Date: May 2003
Revision 1.0

Winbond Electronics Corp.

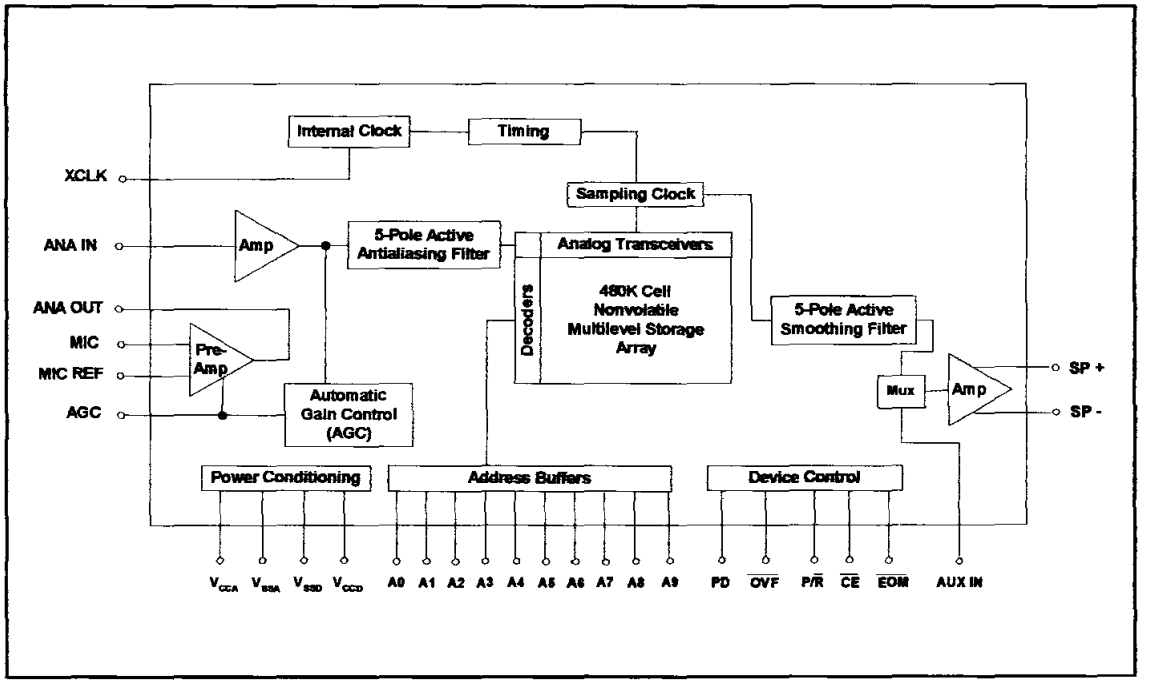
1. GENERAL DESCRIPTION

Winbond's ISD2500 ChipCorder® Series provide high-quality, single-chip, Record/Playback solutions for 60- to 120-second messaging applications. The CMOS devices include an on-chip oscillator, microphone preamplifier, automatic gain control, antialiasing filter, smoothing filter, speaker amplifier, and high density multi-level storage array. In addition, the ISD2500 is microcontroller compatible, allowing complex messaging and addressing to be achieved. Recordings are stored into on-chip nonvolatile memory cells, providing zero-power message storage. This unique, single-chip solution is made possible through Winbond's patented multilevel storage technology. Voice and audio signals are stored directly into memory in their natural form, providing high-quality, solid-state voice reproduction.

2. FEATURES

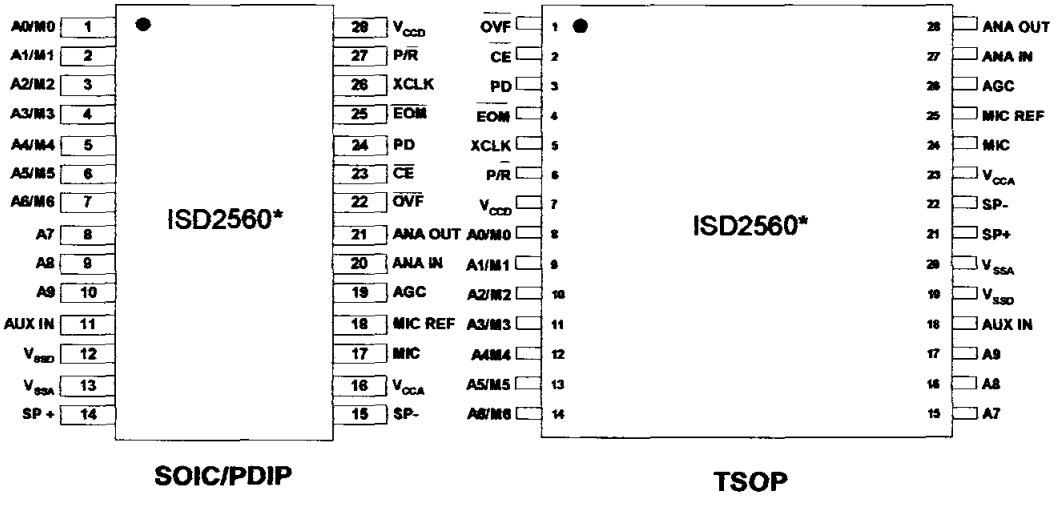
- Easy-to-use single-chip, voice record/playback solution
- High-quality, natural voice/audio reproduction
- Single-chip with duration of 60, 75, 90, or 120 seconds.
- Manual switch or microcontroller compatible
- Playback can be edge- or level-activated
- Directly cascadable for longer durations
- Automatic power-down (push-button mode)
  - Standby current 1 µA (typical)
- Zero-power message storage
  - Eliminates battery backup circuits
- Fully addressable to handle multiple messages
- 100-year message retention (typical)
- 100,000 record cycles (typical)
- On-chip clock source
- Programmer support for play-only applications
- Single +5 volt power supply
- Available in die form, PDIP, SOIC and TSOP packaging
- Temperature = die (0°C to +50°C) and package (0°C to +70°C)

3. BLOCK DIAGRAM



4. TABLE OF CONTENTS

5. PIN CONFIGURATION



* Same pinouts for ISD2575 / 2590 / 25120 products

6. PIN DESCRIPTION

PIN NAME	PIN NO.		FUNCTION
	SOIC/ PDIP	TSOP	
Ax/Mx	1-10/ 1-7	8-17/ 8-14	**Address/Mode Inputs**: The Address/Mode Inputs have two functions depending on the level of the two Most Significant Bits (MSB) of the address pins (A8 and A9). If either or both of the two MSBs are LOW, the inputs are all interpreted as address bits and are used as the start address for the current record or playback cycle. The address pins are inputs only and do not output any internal address information during the operation. Address inputs are latched by the falling edge of $\overline{CE}$. If both MSBs are HIGH, the Address/Mode inputs are interpreted as Mode bits according to the Operational Mode table on page 12. There are six operational modes (M0...M6) available as indicated in the table. It is possible to use multiple operational modes simultaneously. Operational Modes are sampled on each falling edge of $\overline{CE}$, and thus Operational Modes and direct addressing are mutually exclusive.
AUX IN	11	18	**Auxiliary Input:** The Auxiliary Input is multiplexed through to the output amplifier and speaker output pins when $\overline{CE}$ is HIGH, P/$\overline{R}$ is HIGH, and playback is currently not active or if the device is in playback overflow. When cascading multiple ISD2500 devices, the AUX IN pin is used to connect a playback signal from a following device to the previous output speaker drivers. For noise considerations, it is suggested that the auxiliary input not be driven when the storage array is active.
V_{SSA}, V_{SSD}	13, 12	20, 19	**Ground**: The ISD2500 series of devices utilizes separate analog and digital ground busses. These pins should be connected separately through a low-impedance path to power supply ground.
SP+/SP-	14/15	21/22	**Speaker Outputs**: All devices in the ISD2500 series include an on-chip differential speaker driver, capable of driving 50 mW into 16 Ω from AUX IN (12.2mW from memory). [1] The speaker outputs are held at V_{SSA} levels during record and power down. It is therefore not possible to parallel speaker outputs of multiple ISD2500 devices or the outputs of other speaker drivers. [2] A single-end output may be used (including a coupling capacitor between the SP pin and the speaker). These outputs may be used individually with the output signal taken from either pin. However, the use of single-end output results in a 1 to 4 reduction in its output power.

[1] Connection of speaker outputs in parallel may cause damage to the device.
[2] Never ground or drive an unused speaker output.

PIN NAME	PIN NO.		FUNCTION
	SOIC/ PDIP	TSOP	
$\overline{OVF}$	22	1	**Overflow**: This signal pulses LOW at the end of memory array, indicating the device has been filled and the message has overflowed. The $\overline{OVF}$ output then follows the $\overline{CE}$ input until a PD pulse has reset the device. This pin can be used to cascade several ISD2500 devices together to increase record/playback durations.
$\overline{CE}$	23	2	**Chip Enable**: The $\overline{CE}$ input pin is taken LOW to enable all playback and record operations. The address pins and playback/record pin ($P/\overline{R}$) are latched by the falling edge of $\overline{CE}$. $\overline{CE}$ has additional functionality in the M6 (Push-Button) Operational Mode as described in the Operational Mode section.
PD	24	3	**Power Down**: When neither record nor playback operation, the PD pin should be pulled HIGH to place the part in standby mode (see I_{SB} specification). When overflow ($\overline{OVF}$) pulses LOW for an overflow condition, PD should be brought HIGH to reset the address pointer back to the beginning of the memory array. The PD pin has additional functionality in the M6 (Push-Button) Operation Mode as described in the Operational Mode section.
$\overline{EOM}$	25	4	**End-Of-Message**: A nonvolatile marker is automatically inserted at the end of each recorded message. It remains there until the message is recorded over. The $\overline{EOM}$ output pulses LOW for a period of T_{EOM} at the end of each message. In addition, the ISD2500 series has an internal V_{CC} detect circuit to maintain message integrity should V_{CC} fall below 3.5V. In this case, $\overline{EOM}$ goes LOW and the device is fixed in Playback-only mode. When the device is configured in Operational Mode M6 (Push-Button Mode), this pin provides an active-HIGH signal, indicating the device is currently recording or playing. This signal can conveniently drive an LED for visual indicator of a record or playback operation in process.

<table>
<tr><th rowspan="2">PIN NAME</th><th colspan="2">PIN NO.</th><th rowspan="2">FUNCTION</th></tr>
<tr><th>SOIC/ PDIP</th><th>TSOP</th></tr>
<tr><td>XCLK</td><td>26</td><td>5</td><td>External Clock: The external clock input has an internal pull-down device. The device is configured at the factory with an internal sampling clock frequency centered to ±1 percent of specification. The frequency is then maintained to a variation of ±2.25 percent over the entire commercial temperature and operating voltage ranges. If greater precision is required, the device can be clocked through the XCLK pin as follows:
<table>
<tr><th>Part Number</th><th>Sample Rate</th><th>Required Clock</th></tr>
<tr><td>ISD2560</td><td>8.0 kHz</td><td>1024 kHz</td></tr>
<tr><td>ISD2575</td><td>6.4 kHz</td><td>819.2 kHz</td></tr>
<tr><td>ISD2590</td><td>5.3 kHz</td><td>682.7 kHz</td></tr>
<tr><td>ISD25120</td><td>4.0 kHz</td><td>512 kHz</td></tr>
</table>
These recommended clock rates should not be varied because the antialiasing and smoothing filters are fixed, and aliasing problems can occur if the sample rate differs from the one recommended. The duty cycle on the input clock is not critical, as the clock is immediately divided by two. If the XCLK is not used, this input must be connected to ground.</td></tr>
<tr><td>P/$\overline{R}$</td><td>27</td><td>6</td><td>Playback/Record: The P/$\overline{R}$ input pin is latched by the falling edge of the $\overline{CE}$ pin. A HIGH level selects a playback cycle while a LOW level selects a record cycle. For a record cycle, the address pins provide the starting address and recording continues until PD or $\overline{CE}$ is pulled HIGH or an overflow is detected (i.e. the chip is full). When a record cycle is terminated by pulling PD or $\overline{CE}$ HIGH, then End-Of-Message ($\overline{EOM}$) marker is stored at the current address in memory. For a playback cycle, the address inputs provide the starting address and the device will play until an $\overline{EOM}$ marker is encountered. The device can continue to pass an $\overline{EOM}$ marker if $\overline{CE}$ is held LOW in address mode, or in an Operational Mode. (See Operational Modes section)</td></tr>
</table>

7. FUNCTIONAL DESCRIPTION

7.1. DETAILED DESCRIPTION

Speech/Sound Quality

The Winbond's ISD2500 series includes devices offered at 4.0, 5.3, 6.4, and 8.0 kHz sampling frequencies, allowing the user a choice of speech quality options. Increasing the duration within a product series decreases the sampling frequency and bandwidth, which affects the sound quality. Please refer to the ISD2560/75/90/120 Product Summary table below to compare the duration, sampling frequency and filter pass band.

The speech samples are stored directly into the on-chip nonvolatile memory without any digitization and compression associated like other solutions. Direct analog storage provides a very true, natural sounding reproduction of voice, music, tones, and sound effects not available with most solid state digital solutions.

Duration

To meet various system requirements, the ISD2560/75/90/120 products offer single-chip solutions at 60, 75, 90, and 120 seconds. Parts may also be cascaded together for longer durations.

TABLE 1: ISD2560/75/90/120 PRODUCT SUMMARY

Part Number	Duration (Seconds)	Input Sample Rate (kHz)	Typical Filter Pass Band * (kHz)
ISD2560	60	8.0	3.4
ISD2575	75	6.4	2.7
ISD2590	90	5.3	2.3
ISD25120	120	4.0	1.7

* 3db roll-off point

EEPROM Storage

One of the benefits of Winbond's ChipCorder® technology is the use of on-chip nonvolatile memory, providing zero-power message storage. The message is retained for up to 100 years typically without power. In addition, the device can be re-recorded typically over 100,000 times.

Microcontroller Interface

In addition to its simplicity and ease of use, the ISD2500 series includes all the interfaces necessary for microcontroller-driven applications. The address and control lines can be interfaced to a microcontroller and manipulated to perform a variety of tasks, including message assembly, message concatenation, predefined fixed message segmentation, and message management.

Programming

The ISD2500 series is also ideal for playback-only applications, where single or multiple messages are referenced through buttons, switches, or a microcontroller. Once the desired message configuration is created, duplicates can easily be generated via a gang programmer.

7.2. OPERATIONAL MODES

The ISD2500 series is designed with several built-in Operational Modes that provide maximum functionality with minimum external components. These modes are described in details as below. The Operational Modes are accessed via the address pins and mapped beyond the normal message address range. When the two Most Significant Bits (MSB), A8 and A9, are HIGH, the remaining address signals are interpreted as mode bits and not as address bits. Therefore, Operational Modes and direct addressing are not compatible and cannot be used simultaneously.

There are two important considerations for using Operational Modes. First, all operations begin initially at address 0 of its memory. Later operations can begin at other address locations, depending on the Operational Mode(s) chosen. In addition, the address pointer is reset to 0 when the device is changed from record to playback, playback to record (except M6 mode), or when a Power-Down cycle is executed.

Second, Operational Modes are executed when $\overline{CE}$ goes LOW. This Operational Mode remains in effect until the next LOW-going $\overline{CE}$ signal, at which point the current mode(s) are sampled and executed.

TABLE 2: OPERATIONAL MODES

Mode [1]	Function	Typical Use	Jointly Compatible [2]
M0	Message cueing	Fast-forward through messages	M4, M5, M6
M1	Delete $\overline{EOM}$ markers	Position $\overline{EOM}$ marker at the end of the last message	M3, M4, M5, M6
M2	Not applicable	Reserved	N/A
M3	Looping	Continuous playback from Address 0	M1, M5, M6
M4	Consecutive addressing	Record/playback multiple consecutive messages	M0, M1, M5
M5	$\overline{CE}$ level-activated	Allows message pausing	M0, M1, M3, M4
M6	Push-button control	Simplified device interface	M0, M1, M3

[1] Besides mode pin needed to be "1", A8 and A9 pin are also required to be "1" in order to enter into the related operational mode.

[2] Indicates additional Operational Modes which can be used simultaneously with the given mode.

7.2.1. Operational Modes Description

The Operational Modes can be used in conjunction with a microcontroller, or they can be hardwired to provide the desired system operation.

M0 – Message Cueing

Message Cueing allows the user to skip through messages, without knowing the actual physical addresses of each message. Each $\overline{CE}$ LOW pulse causes the internal address pointer to skip to the next message. This mode is used for playback only, and is typically used with the M4 Operational Mode.

M1 – Delete $\overline{EOM}$ Markers

The M1 Operational Mode allows sequentially recorded messages to be combined into a single message with only one $\overline{EOM}$ marker set at the end of the final message. When this Operational Mode is configured, messages recorded sequentially are played back as one continuous message.

M2 – Unused

When Operational Modes are selected, the M2 pin should be LOW.

M3 – Message Looping

The M3 Operational Mode allows for the automatic, continuously repeated playback of the message located at the beginning of the address space. A message can completely fill the ISD2500 device and will loop from beginning to end without $\overline{OVF}$ going LOW.

M4 – Consecutive Addressing

During normal operation, the address pointer will reset when a message is played through an $\overline{EOM}$ marker. The M4 Operational Mode inhibits the address pointer reset on $\overline{EOM}$, allowing messages to be played back consecutively.

M5 - $\overline{CE}$-Level Activated

The default mode for ISD2500 devices is for $\overline{CE}$ to be edge-activated on playback and level-activated on record. The M5 Operational Mode causes the $\overline{CE}$ pin to be interpreted as level-activated as opposed to edge-activated during playback. This is especially useful for terminating playback operations using the $\overline{CE}$ signal. In this mode, $\overline{CE}$ LOW begins a playback cycle, at the beginning of the device memory. The playback cycle continues as long as $\overline{CE}$ is held LOW. When $\overline{CE}$ goes HIGH, playback will immediately end. A new $\overline{CE}$ LOW will restart the message from the beginning unless M4 is also HIGH.

M6 – Push-Button Mode

The ISD2500 series contain a Push-Button Operational Mode. The Push-Button Mode is used primarily in very low-cost applications and is designed to minimize external circuitry and components, thereby reducing system cost. In order to configure the device in Push-Button Operational Mode, the two most significant address bits must be HIGH, and the M6 mode pin must also be HIGH. A device in this mode always powers down at the end of each playback or record cycle after $\overline{CE}$ goes HIGH.

When this operational mode is implemented, three of the pins on the device have alternate functionality as described in the table below.

TABLE 3: ALTERNATE FUNCTIONALITY IN PINS

Pin Name	Alternate Functionality in Push-Button Mode
$\overline{CE}$	Start/Pause Push-Button (LOW pulse-activated)
PD	Stop/Reset Push-Button (HIGH pulse-activated)
$\overline{EOM}$	Active-HIGH Run Indicator

$\overline{CE}$ (START/PAUSE)

In Push-Button Operational Mode, $\overline{CE}$ acts as a LOW-going pulse-activated START/PAUSE signal. If no operation is currently in progress, a LOW-going pulse on this signal will initiate a playback or record cycle according to the level on the P/$\overline{R}$ pin. A subsequent pulse on the $\overline{CE}$ pin, before an $\overline{EOM}$ is reached in playback or an overflow condition occurs, will pause the current operation, and the address counter is not reset. Another $\overline{CE}$ pulse will cause the device to continue the operation from the place where it is paused.

PD (STOP/RESET)

In Push-Button Operational Mode, PD acts as a HIGH-going pulse-activated STOP/RESET signal. When a playback or record cycle is in progress and a HIGH-going pulse is observed on PD, the current cycle is terminated and the address pointer is reset to address 0, the beginning of the message space.

$\overline{EOM}$ (RUN)

In Push-Button Operational Mode, $\overline{EOM}$ becomes an active-HIGH RUN signal which can be used to drive an LED or other external device. It is HIGH whenever a record or playback operation is in progress.

Recording in Push-Button Mode

1. The PD pin should be LOW, usually using a pull-down resistor.

2. The P/$\overline{R}$ pin is taken LOW.
3. The $\overline{CE}$ pin is pulsed LOW. Recording starts, $\overline{EOM}$ goes HIGH to indicate an operation in progress.
4. When the $\overline{CE}$ pin is pulsed LOW. Recording pauses, $\overline{EOM}$ goes back LOW. The internal address pointers are not cleared, but the $\overline{EOM}$ marker is stored in memory to indicate as the message end. The P/$\overline{R}$ pin may be taken HIGH at this time. Any subsequent $\overline{CE}$ would start a playback at address 0.
5. The $\overline{CE}$ pin is pulsed LOW. Recording starts at the next address after the previous set $\overline{EOM}$ marker. $\overline{EOM}$ goes back HIGH.[3]
6. When the recording sequences are finished, the final $\overline{CE}$ pulse LOW will end the last record cycle, leaving a set $\overline{EOM}$ marker at the message end. Recording may also be terminated by a HIGH level on PD, which will leave a set $\overline{EOM}$ marker.

Playback in Push-Button Mode

1. The PD pin should be LOW.
2. The P/$\overline{R}$ pin is taken HIGH.
3. The $\overline{CE}$ pin is pulsed LOW. Playback starts, $\overline{EOM}$ goes HIGH to indicate an operation in progress.
4. If the $\overline{CE}$ pin is pulsed LOW or an $\overline{EOM}$ marker is encountered during an operation, the part will pause. The internal address pointers are not cleared, and $\overline{EOM}$ goes back LOW. The P/$\overline{R}$ pin may be changed at this time. A subsequent record operation would not reset the address pointers and the recording would begin where playback ended.
5. $\overline{CE}$ is again pulsed LOW. Playback starts where it left off, with $\overline{EOM}$ going HIGH to indicate an operation in progress.
6. Playback continues as in steps 4 and 5 until PD is pulsed HIGH or overflow occurs.
7. If in overflow, pulling $\overline{CE}$ LOW will reset the address pointer and start playback from the beginning. After a PD pulse, the part is reset to address 0.

Note: Push-Button Mode can be used in conjunction with modes M0, M1, and M3.

[3] If the M1 Operational Mode pin is also HIGH, the just previously written $\overline{EOM}$ bit is erased, and recording starts at that address.

Winbond Electronics Corp.

Good Audio Design Practices

Winbond products are very high-quality single-chip voice recording and playback systems. To ensure the highest quality voice reproduction, it is important that good audio design practices on layout and power supply decoupling be followed. See Application Information or below links for details.

Good Audio Design Practices

http://www.winbond-usa.com/products/isd_products/chipcorder/applicationinfo/apin11.pdf

Single-Chip Board Layout Diagrams

http://www.winbond-usa.com/products/isd_products/chipcorder/applicationinfo/apin12.pdf

8. TIMING DIAGRAMS

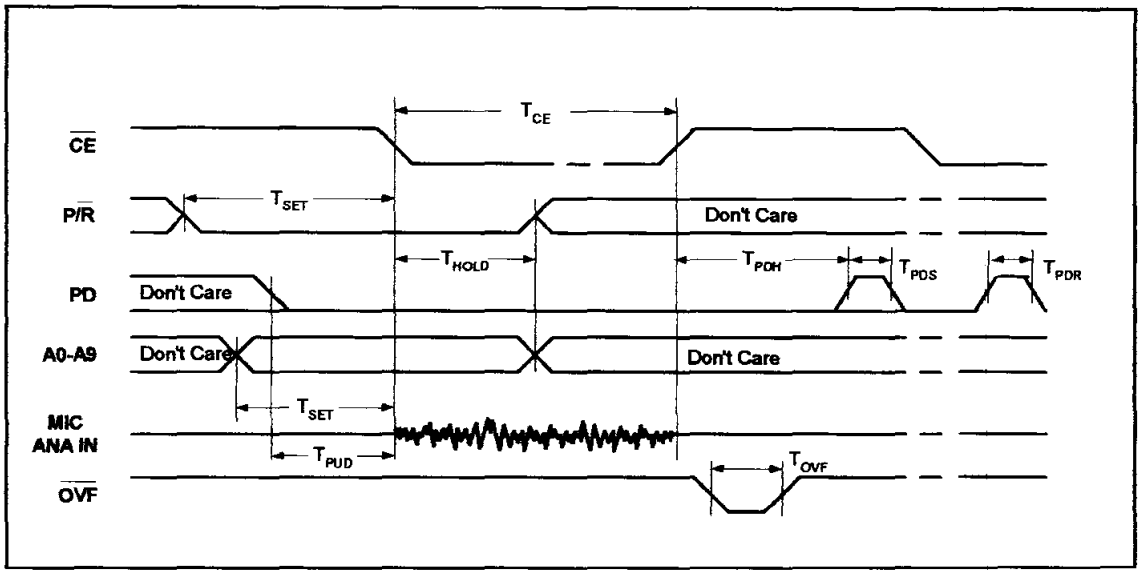


FIGURE 1: RECORD

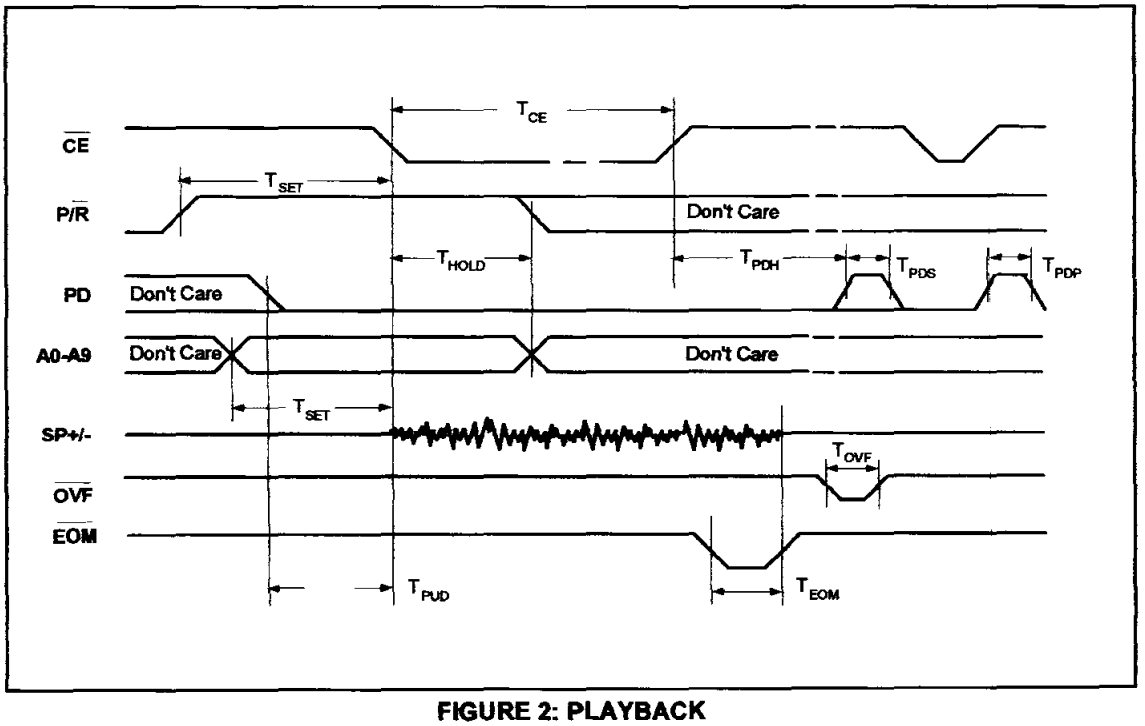


FIGURE 2: PLAYBACK

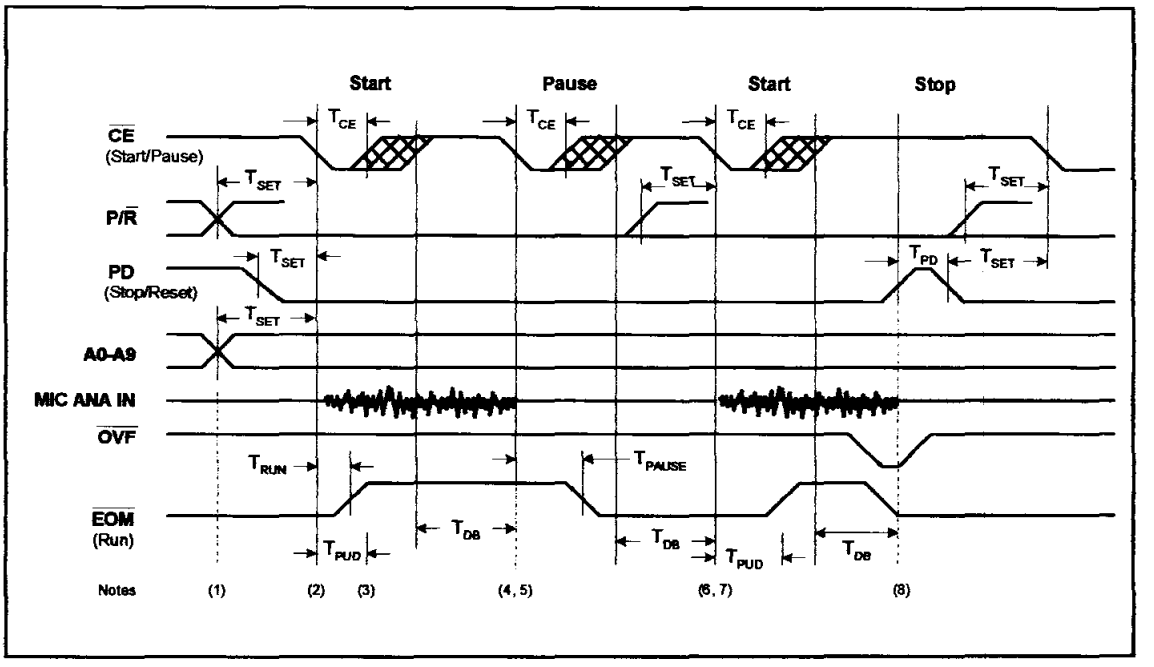


FIGURE 3: PUSH-BUTTON MODE RECORD

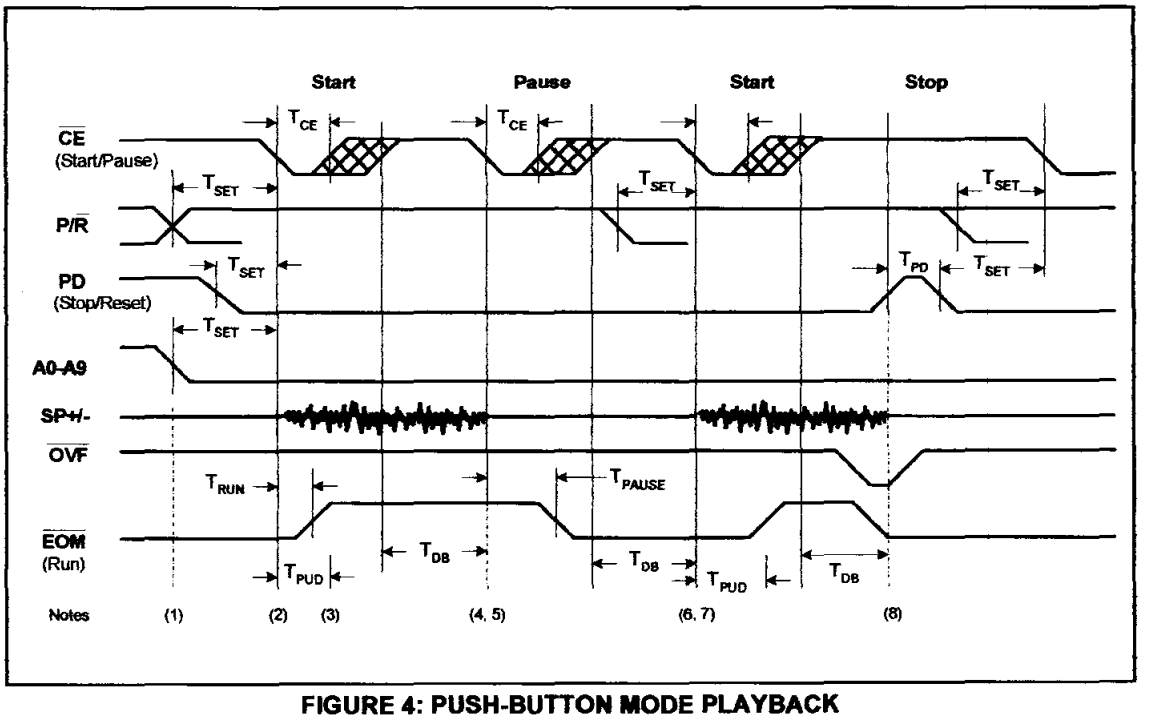


FIGURE 4: PUSH-BUTTON MODE PLAYBACK

Notes for Push-Button modes:

1. A9, A8, and A6 = 1 for push-button operation.
2. The first $\overline{CE}$ LOW pulse performs a start function.
3. The part will begin to play or record after a power-up delay T_{PUD}.
4. The part must have $\overline{CE}$ HIGH for a debounce period T_{DB} before it will recognize another falling edge of $\overline{CE}$ and pause.
5. The second $\overline{CE}$ LOW pulse, and every even pulse thereafter, performs a Pause function.
6. Again, the part must have $\overline{CE}$ HIGH for a debounce period T_{DB} before it will recognize another falling edge of $\overline{CE}$, which would restart an operation. In addition, the part will not do an internal power down until $\overline{CE}$ is HIGH for the T_{DB} time.
7. The third $\overline{CE}$ LOW pulse, and every odd pulse thereafter, performs a Resume function.
8. At any time, a HIGH level on PD will stop the current function, reset the address counter, and power down the device.

9. ABSOLUTE MAXIMUM RATINGS

TABLE 4: ABSOLUTE MAXIMUM RATINGS (DIE)

CONDITION	VALUE
Junction temperature	150°C
Storage temperature range	-65°C to +150°C
Voltage applied to any pad	(V_{SS} –0.3V) to (V_{CC} +0.3V)
Voltage applied to any pad (Input current limited to ±20mA)	(V_{SS} –1.0V) to (V_{CC} +1.0V)
V_{CC} – V_{SS}	-0.3V to +7.0V

TABLE 5: ABSOLUTE MAXIMUM RATINGS (PACKAGED PARTS)

CONDITION	VALUE
Junction temperature	150°C
Storage temperature range	-65°C to +150°C
Voltage applied to any pin	(V_{SS} –0.3V) to (V_{CC} +0.3V)
Voltage applied to any pin (Input current limited to ±20 mA)	(V_{SS} –1.0V) to (V_{CC} +1.0V)
Lead temperature (Soldering – 10sec)	300°C
V_{CC} – V_{SS}	-0.3V to +7.0V

Note: Stresses above those listed may cause permanent damage to the device. Exposure to the absolute maximum ratings may affect device reliability and performance. Functional operation is not implied at these conditions.

9.1 OPERATING CONDITIONS

TABLE 6: OPERATING CONDITIONS (DIE)

CONDITION	VALUE
Commercial operating temperature range	0°C to +50°C
Supply voltage (V_{CC}) [1]	+4.5V to +6.5V
Ground voltage (V_{SS}) [2]	0V

TABLE 7: OPERATING CONDITIONS (PACKAGED PARTS)

CONDITION	VALUE
Commercial operating temperature range [3]	0°C to +70°C
Supply voltage (V_{CC}) [1]	+4.5V to +5.5V
Ground voltage (V_{SS}) [2]	0V

[1] $V_{CC} = V_{CCA} = V_{CCD}$

[2] $V_{SS} = V_{SSA} = V_{SSD}$

[3] Case Temperature

10. ELECTRICAL CHARACTERISTICS

10.1. PARAMETERS FOR PACKAGED PARTS

TABLE 8: DC PARAMETERS – Packaged Parts

PARAMETER	SYMBOL	MIN[2]	TYP[1]	MAX[2]	UNITS	CONDITIONS
Input Low Voltage	V_{IL}			0.8	V	
Input High Voltage	V_{IH}	2.0			V	
Output Low Voltage	V_{OL}			0.4	V	I_{OL} = 4.0 mA
Output High Voltage	V_{OH}	V_{CC} - 0.4			V	I_{OH} = -10 µA
$\overline{OVF}$ Output High Voltage	V_{OH1}	2.4			V	I_{OH} = -1.6 mA
$\overline{EOM}$ Output High Voltage	V_{OH2}	V_{CC} – 1.0	V_{CC} - 0.8		V	I_{OH} = -3.2 mA
V_{CC} Current (Operating)	I_{CC}		25	30	mA	R_{EXT} = ∞ [3]
V_{CC} Current (Standby)	I_{SB}		1	10	µA	[3]
Input Leakage Current	I_{IL}			±1	µA	
Input Current HIGH w/Pull Down	I_{ILPD}			130	µA	Force V_{CC} [4]
Output Load Impedance	R_{EXT}	16			Ω	Speaker Load
Preamp Input Resistance	R_{MIC}	4	9	15	KΩ	MIC and MIC REF Pins
AUX IN Input Resistance	R_{AUX}	5	11	20	KΩ	
ANA IN Input Resistance	$R_{ANA\ IN}$	2.3	3	5	KΩ	
Preamp Gain 1	A_{PRE1}	21	24	26	dB	AGC = 0.0V
Preamp Gain 2	A_{PRE2}		-15	5	dB	AGC = 2.5V
AUX IN/SP+ Gain	A_{AUX}		0.98	1.0	V/V	
ANA IN to SP+/- Gain	A_{ARP}	21	23	26	dB	
AGC Output Resistance	R_{AGC}	2.5	5	9.5	KΩ	

Notes:

[1] Typical values @ T_A = 25° and V_{CC} = 5.0V.

[2] All Min/Max limits are guaranteed by Winbond via electrical testing or characterization. Not all specifications are 100 percent tested.

[3] V_{CCA} and V_{CCD} connected together.

[4] XCLK pin only.

Winbond Electronics Corp.

TABLE 9: AC PARAMETERS – Packaged Parts

CHARACTERISTIC	SYMBOL	MIN[2]	TYP[1]	MAX[2]	UNITS	CONDITIONS
Sampling Frequency	F_S					
ISD2560			8.0		kHz	[7]
ISD2575			6.4		kHz	[7]
ISD2590			5.3		kHz	[7]
ISD25120			4.0		kHz	[7]
Filter Pass Band	F_{CF}					
ISD2560			3.4		kHz	3 dB Roll-Off Point[3][8]
ISD2575			2.7		kHz	3 dB Roll-Off Point[3][8]
ISD2590			2.3		kHz	3 dB Roll-Off Point[3][8]
ISD25120			1.7		kHz	3 dB Roll-Off Point[3][8]
Record Duration	T_{REC}					
ISD2560		58.1	60.0	62.0	sec	Commercial Operation[7]
ISD2575		72.6	75.0	77.5	sec	Commercial Operation[7]
ISD2590		87.1	90.0	93.0	sec	Commercial Operation[7]
ISD25120		116.1	120.0	123.9	sec	Commercial Operation[7]
Playback Duration	T_{PLAY}					
ISD2560		58.1	60.0	62.0	sec	Commercial Operation
ISD2575		72.6	75.0	77.5	sec	Commercial Operation
ISD2590		87.1	90.0	93.0	sec	Commercial Operation
ISD25120		116.1	120.0	123.9	sec	Commercial Operation
$\overline{CE}$ Pulse Width	T_{CE}		100		nsec	
Control/Address Setup Time	T_{SET}		300		nsec	
Control/Address Hold Time	T_{HOLD}		0		nsec	
Power-Up Delay	T_{PUD}					
ISD2560		24.1	25.0	27.8	msec	Commercial Operation
ISD2575		30.2	31.3	34.3	msec	Commercial Operation
ISD2590		36.2	37.5	40.8	msec	Commercial Operation
ISD25120		48.2	50.0	53.6	msec	Commercial Operation
PD Pulse Width (record)	T_{PDR}					
ISD2560			25.0		msec	
ISD2575			31.25		msec	
ISD2590			37.5		msec	
ISD25120			50.0		msec	

TABLE 9: AC PARAMETERS – Packaged Parts (Cont'd)

CHARACTERISTIC	SYMBOL	MIN[2]	TYP[1]	MAX[2]	UNITS	CONDITIONS
PD Pulse Width (Play)	T_{PDP}					
ISD2560			12.5		msec	
ISD2575			15.625		msec	
ISD2590			18.75		msec	
ISD25120			25.0		msec	
PD Pulse Width (Static)	T_{PDS}		100		nsec	[6]
Power Down Hold	T_{PDH}		0		nsec	
$\overline{EOM}$ Pulse Width	T_{EOM}					
ISD2560			12.5		msec	
ISD2575			15.625		msec	
ISD2590			18.75		msec	
ISD25120			25.0		msec	
Overflow Pulse Width	T_{OVF}		6.5		µsec	
Total Harmonic Distortion	THD		1	2	%	@ 1 kHz
Speaker Output Power	P_{OUT}		12.2	50	mW	R_{EXT} = 16 Ω[4]
Voltage Across Speaker Pins	V_{OUT}			2.5	V p-p	R_{EXT} = 600 Ω
MIC Input Voltage	V_{IN1}			20	mV	Peak-to-Peak[5]
ANA IN Input Voltage	V_{IN2}			50	mV	Peak-to-Peak
AUX Input Voltage	V_{IN3}			1.25	V	Peak-to-Peak; R_{EXT} = 16 Ω

Notes:

[1] Typical values @ T_A = 25°C and V_{CC} = 5.0V.

[2] All Min/Max limits are guaranteed by Winbond via electrical testing or characterization. Not all specifications are 100 percent tested.

[3] Low-frequency cutoff depends upon the value of external capacitors (see Pin Descriptions)

[4] From AUX IN; if ANA IN is driven at 50 mV p-p, the P_{OUT} = 12.2 mW, typical.

[5] With 5.1 K Ω series resistor at ANA IN.

[6] T_{PDS} is required during a static condition, typically overflow.

[7] Sampling Frequency and playback Duration can vary as much as ±2.25 percent over the commercial temperature range. For greater stability, an external clock can be utilized (see Pin Descriptions)

[8] Filter specification applies to the antialiasing filter and the smoothing filter. Therefore, from input to output, expect a 6 dB drop by nature of passing through both filters.

10.1.1. Typical Parameter Variation with Voltage and Temperature (Packaged Parts)

Chart 1: Record Mode Operating Current (I_{CC})

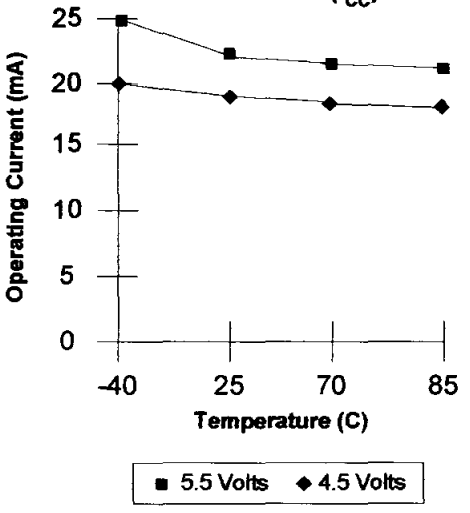


Chart 3: Standby Current (I_{SB})

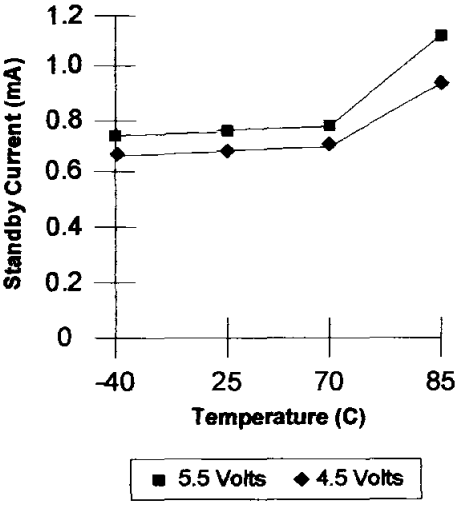


Chart 2: Total Harmonic Distortion

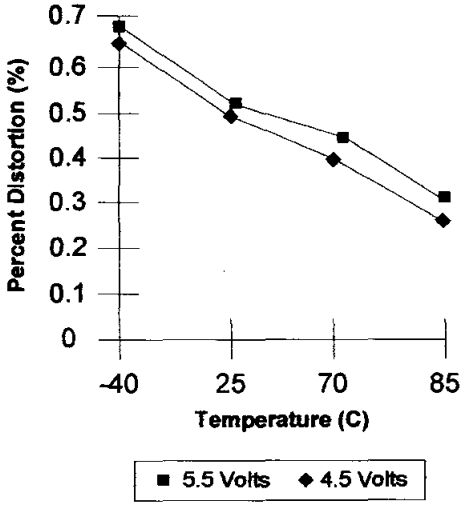
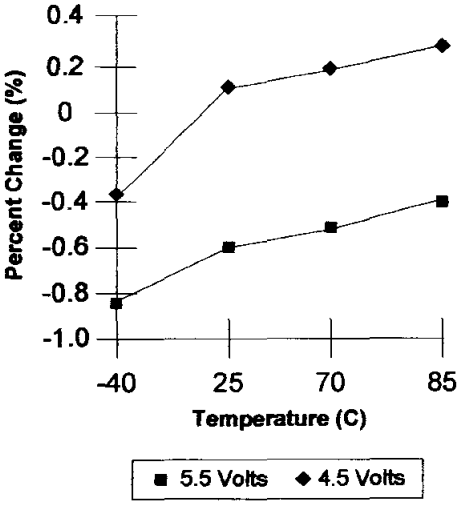


Chart 4: Oscillator Stability



10.2. PARAMETERS FOR DIE

TABLE 10: DC PARAMETERS – Die

PARAMETER	SYMBOL	MIN[2]	TYP[1]	MAX[2]	UNITS	CONDITIONS
Input Low Voltage	V_{IL}			0.8	V	
Input High Voltage	V_{IH}	2.0			V	
Output Low Voltage	V_{OL}			0.4	V	I_{OL} = 4.0 mA
Output High Voltage	V_{OH}	V_{CC} - 0.4			V	I_{OH} = -10 µA
$\overline{OVF}$ Output High Voltage	V_{OH1}	2.4			V	I_{OH} = -1.6 mA
$\overline{EOM}$ Output High Voltage	V_{OH2}	V_{CC} – 1.0	V_{CC} - 0.8		V	I_{OH} = -3.2 mA
V_{CC} Current (Operating)	I_{CC}		25	30	mA	R_{EXT} = ∞ [3]
V_{CC} Current (Standby)	I_{SB}		1	10	µA	[2]
Input Leakage Current	I_{IL}			±1	µA	
Input Current HIGH w/Pull Down	I_{ILPD}			130	µA	Force V_{CC} [4]
Output Load Impedance	R_{EXT}	16			Ω	Speaker Load
Preamp IN Input Resistance	R_{MIC}	4	9	15	KΩ	MIC and MIC REF Pads
AUX IN Input Resistance	R_{AUX}	5	11	20	KΩ	
ANA IN Input Resistance	$R_{ANA\ IN}$	2.3	3	5	KΩ	
Preamp Gain 1	A_{PRE1}	21	24	26	dB	AGC = 0.0V
Preamp Gain 2	A_{PRE2}		-15	5	dB	AGC = 2.5V
AUX IN/SP+ Gain	A_{AUX}		0.98	1.0	V/V	
ANA IN to SP+/- Gain	A_{ARP}	21	23	26	dB	
AGC Output Resistance	R_{AGC}	2.5	5	9.5	KΩ	

Notes:

[1] Typical values @ T_A = 25°C and V_{CC} = 5.0V.

[2] All Min/Max limits are guaranteed by Winbond via electrical testing or characterization. Not all specifications are 100 percent tested.

[3] V_{CCA} and V_{CCD} connected together.

[4] XCLK pad only.

Winbond Electronics Corp.

TABLE 11: AC PARAMETERS – Die

CHARACTERISTIC	SYMBOL	MIN[2]	TYP[7]	MAX[2]	UNITS	CONDITIONS
Sampling Frequency	F_S					
ISD2560			8.0		kHz	[7]
ISD2575			6.4		kHz	[7]
ISD2590			5.3		kHz	[7]
ISD25120			4.0		kHz	[7]
Filter Pass Band	F_{CF}					
ISD2560			3.4		kHz	3 dB Roll-Off Point[3][8]
ISD2575			2.7		kHz	3 dB Roll-Off Point[3][8]
ISD2590			2.3		kHz	3 dB Roll-Off Point[3][8]
ISD25120			1.7		kHz	3 dB Roll-Off Point[3][8]
Record Duration	T_{REC}					
ISD2560		58.1	60.0	62.0	sec	Commercial Operation[7]
ISD2575		72.6	75.0	77.5	sec	Commercial Operation[7]
ISD2590		87.1	90.0	93.0	sec	Commercial Operation[7]
ISD25120		116.1	120.0	123.9	sec	Commercial Operation[7]
Playback Duration	T_{PLAY}					
ISD2560		58.1	60.0	62.0	sec	Commercial Operation[7]
ISD2575		72.6	75.0	77.5	sec	Commercial Operation[7]
ISD2590		87.1	90.0	93.0	sec	Commercial Operation[7]
ISD25120		116.1	120.0	123.9	sec	Commercial Operation[7]
$\overline{CE}$ Pulse Width	T_{CE}		100		nsec	
Control/Address Setup Time	T_{SET}		300		nsec	
Control/Address Hold Time	T_{HOLD}		0		nsec	
Power-Up Delay	T_{PUD}					
ISD2560		24.1	25.0	27.8	msec	Commercial Operation
ISD2575		30.2	31.3	34.3	msec	Commercial Operation
ISD2590		36.2	37.5	40.8	msec	Commercial Operation
ISD25120		48.2	50.0	53.6	msec	Commercial Operation
PD Pulse Width (Record)	T_{PDR}					
ISD2560			25.0		msec	
ISD2575			31.25		msec	
ISD2590			37.5		msec	
ISD25120			50.0		msec	

TABLE 11: AC PARAMETERS – Die (Cont'd)

CHARACTERISTIC	SYMBOL	MIN[2]	TYP[1]	MAX[2]	UNITS	CONDITIONS
PD Pulse Width (Play)	T_{PDP}					
ISD2560			12.5		msec	
ISD2575			15.625		msec	
ISD2590			18.75		msec	
ISD25120			25.0		msec	
PD Pulse Width (Static)	T_{PDS}		100		nsec	[6]
Power Down Hold	T_{PDH}		0		nsec	
$\overline{EOM}$ Pulse Width	T_{EOM}					
ISD2560			12.5		msec	
ISD2575			15.625		msec	
ISD2590			18.75		msec	
ISD25120			25.0		msec	
Overflow Pulse Width	T_{OVF}		6.5		µsec	
Total Harmonic Distortion	THD		1	3	%	@ 1 kHz
Speaker Output Power	P_{OUT}		12.2	50	mW	R_{EXT} = 16 Ω[4]
Voltage Across Speaker Pins	V_{OUT}			2.5	V p-p	R_{EXT} = 600 Ω
MIC Input Voltage	V_{IN1}			20	mV	Peak-to-Peak[5]
ANA IN Input Voltage	V_{IN2}			50	mV	Peak-to-Peak
AUX Input Voltage	V_{IN3}			1.25	V	Peak-to-Peak; R_{EXT} = 16 Ω

Notes:

[1] Typical values @ T_A = 25°C and V_{CC} = 5.0V.

[2] All Min/Max limits are guaranteed by Winbond via electrical testing or characterization. Not all specifications are 100 percent tested.

[3] Low-frequency cutoff depends upon the value of external capacitors (see Pin Descriptions)

[4] From AUX IN; if ANA IN is driven at 50 mV p-p, the P_{OUT} = 12.2 mW, typical.

[5] With 5.1 K Ω series resistor at ANA IN.

[6] T_{PDS} is required during a static condition, typically overflow.

[7] Sampling Frequency and playback Duration can vary as much as ±2.25 percent over the commercial temperature range. For greater stability, an external clock can be utilized (see Pin Descriptions)

[8] Filter specification applies to the antialiasing filter and the smoothing filter. Therefore, from input to output, expect a 6 dB drop by nature of passing through both filters.

10.2.1. Typical Parameter Variation with Voltage and Temperature (Die)

Chart 5: Record Mode Operating Current (I_{CC})

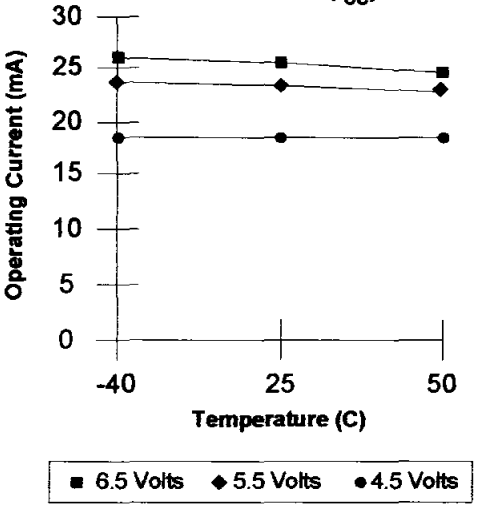


Chart 7: Standby Current (I_{SB})

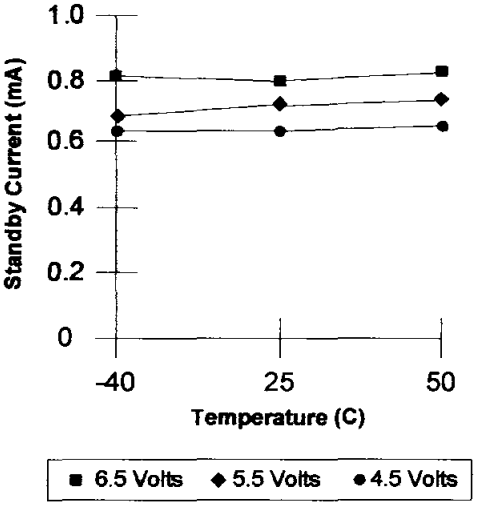


Chart 6: Total Harmonic Distortion

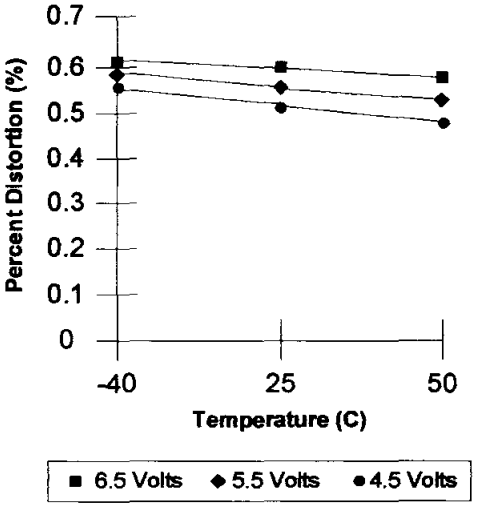
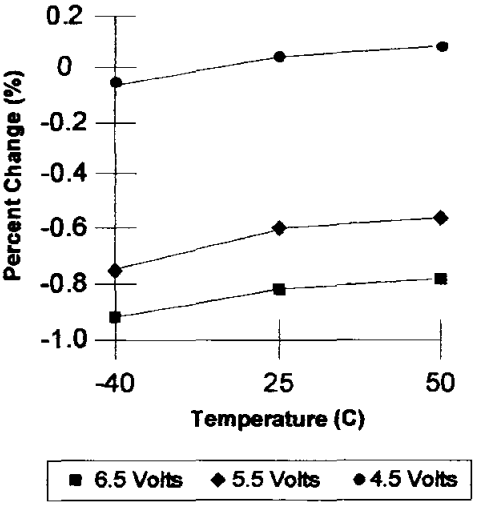


Chart 8: Oscillator Stability



10.3. PARAMETERS FOR PUSH-BUTTON MODE

TABLE 12: PARAMETERS FOR PUSH-BUTTON MODE

PARAMETER	SYMBOL	MIN[2]	TYP[1]	MAX[2]	UNITS	CONDITIONS
$\overline{CE}$ Pulse Width (Start/Pause)	T_{CE}		300		nsec	
Control/Address Setup Time	T_{SET}		300		nsec	
Power-Up Delay	T_{PUD}					
ISD2560			25.0		msec	
ISD2575			31.25		msec	
ISD2590			37.25		msec	
ISD25120			50.0		msec	
PD Pulse Width (Stop/Restart)	T_{PD}		300		nsec	
$\overline{CE}$ to $\overline{EOM}$ HIGH	T_{RUN}	25		400	nsec	
$\overline{CE}$ to $\overline{EOM}$ LOW	T_{PAUSE}	50		400	nsec	
$\overline{CE}$ HIGH Debounce	T_{DB}					
ISD2560		70		105	msec	
ISD2575		85		135	msec	
ISD2590		105		160	msec	
ISD25120		135		215	msec	

Notes:

[1] Typical values @ T_A = 25°C and V_{CC} = 5.0V.

[2] All Min/Max limits are guaranteed by Winbond via electrical testing or characterization. Not all specifications are 100 percent tested.

11. TYPICAL APPLICATION CIRCUIT

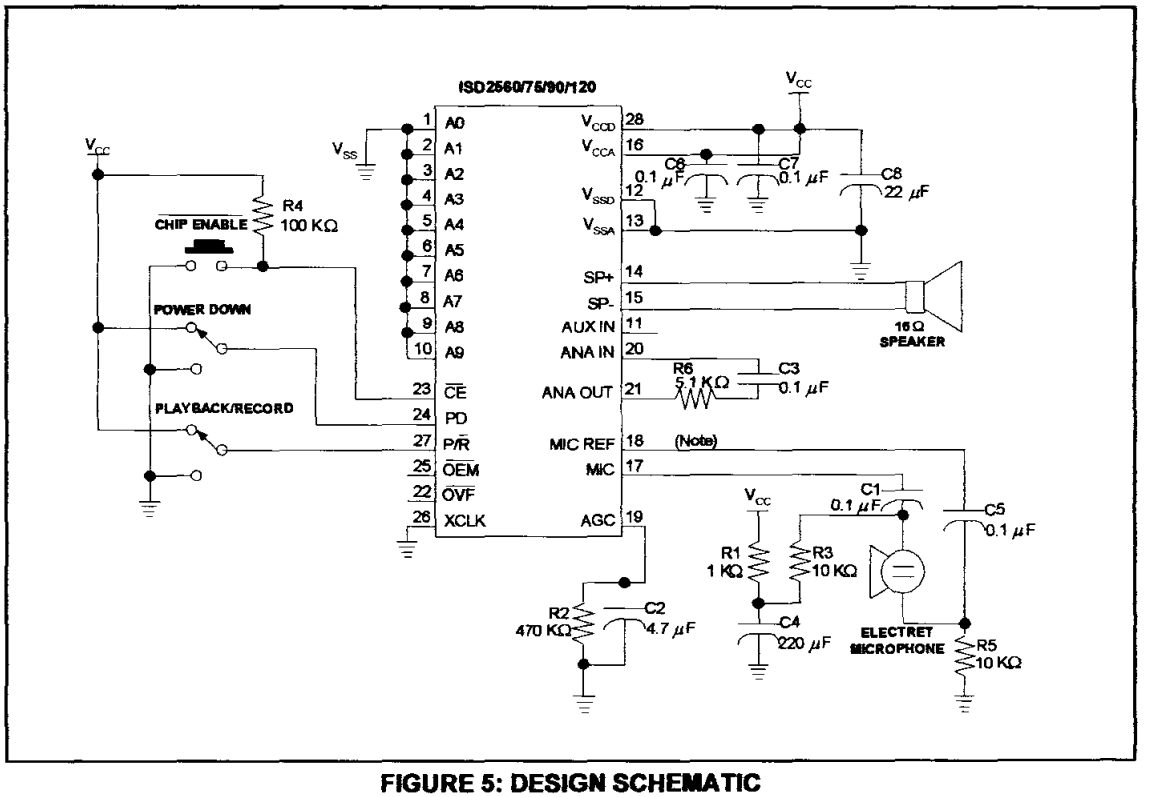


FIGURE 5: DESIGN SCHEMATIC

Note: If desired, pin 18 (PDIP package) may be left unconnected (microphone preamplifier noise will be higher). In this case, pin 18 must not be tied to any other signal or voltage. Additional design example schematics are provided below.

TABLE 13: APPLICATION EXAMPLE – BASIC DEVICE CONTROL

Control Step	Function	Action
1	Power up chip and select Record/Playback Mode	1. PD = LOW, 2. P/$\overline{R}$ = As desired
2	Set message address for record/playback	Set addresses A0-A9
3A	Begin playback	P/$\overline{R}$ = HIGH, $\overline{CE}$ = Pulse LOW
3B	Begin record	P/$\overline{R}$ = LOW, $\overline{CE}$ = LOW
4A	End playback	Automatic
4B	End record	PD or $\overline{CE}$ = HIGH

TABLE 14: APPLICATION EXAMPLE – PASSIVE COMPONENT FUNCTIONS

Part	Function	Comments
R1	Microphone power supply decoupling	Reduces power supply noise
R2	Release time constant	Sets release time for AGC
R3, R5	Microphone biasing resistors	Provides biasing for microphone operation
R4	Series limiting resistor	Reduces level to prevent distortion at higher supply voltages
R6	Series limiting resistor	Reduces level to high supply voltages
C1, C5	Microphone DC-blocking capacitor Low-frequency cutoff	Decouples microphone bias from chip. Provides single-pole low-frequency cutoff and command mode noise rejection.
C2	Attack/Release time constant	Sets attack/release time for AGC
C3	Low-frequency cutoff capacitor	Provides additional pole for low-frequency cutoff
C4	Microphone power supply decoupling	Reduces power supply noise
C6, C7, C8	Power supply capacitors	Filter and bypass of power supply

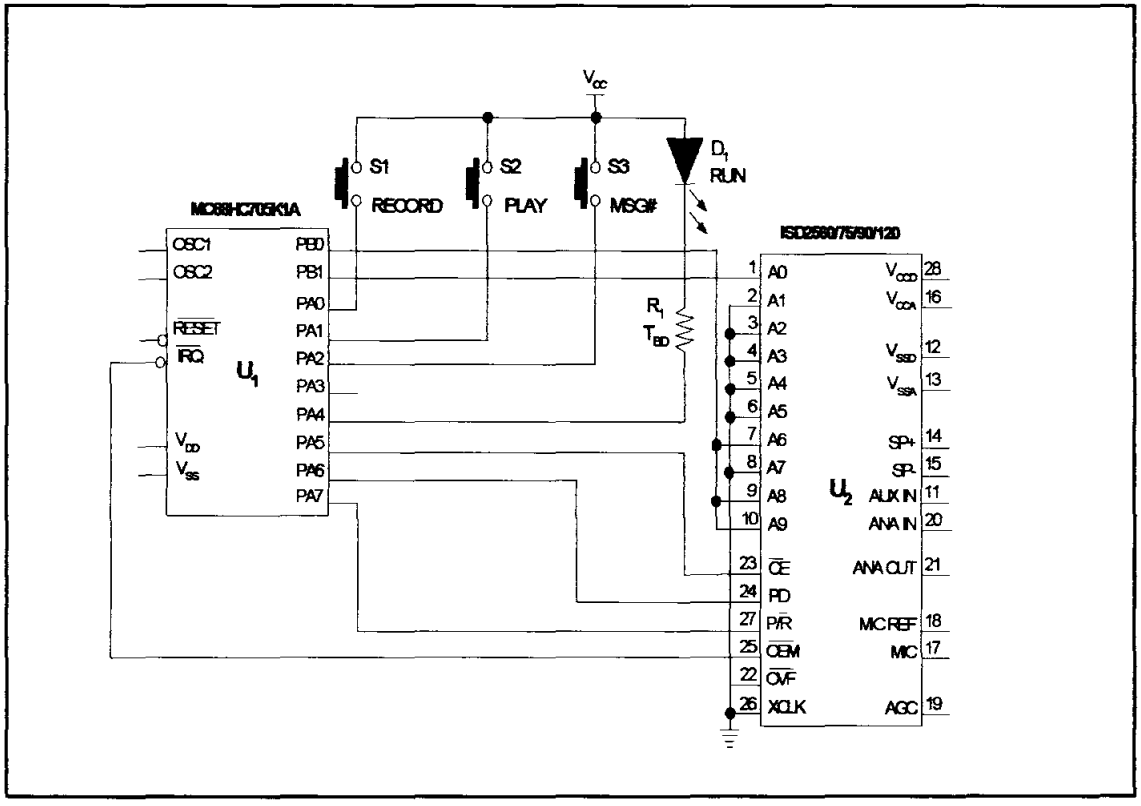


FIGURE 6: ISD2560/75/90/120 APPLICATION EXAMPLE – MICROCONTROLLER/ISD2500 INTERFACE

In this simplified block diagram of a microcontroller application, the Push-Button Mode and message cueing are used. The microcontroller is a 16-pin version with enough port pins for buttons, an LED, and the ISD2500 series device. The software can be written to use three buttons: one each for play and record, and one for message selection. Because the microcontroller is interpreting the buttons and commanding the ISD2500 device, software can be written for any function desired in a particular application.

Note: Winbond does not recommend connecting address lines directly to a microprocessor bus. Address lines should be externally latched.

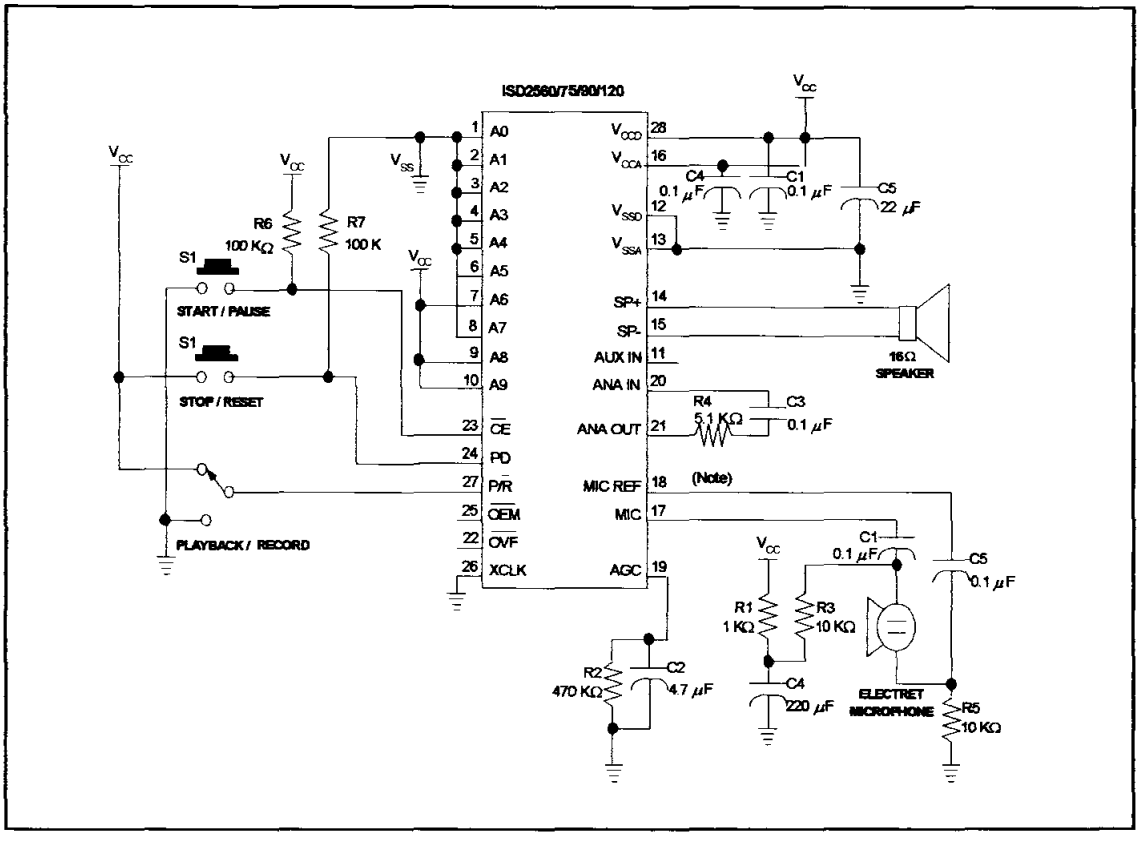


FIGURE 7: ISD2560/75/90/120 APPLICATION EXAMPLE – PUSH-BUTTON

Note: Please refer to page 13 for more details.

TABLE 15: APPLICATION EXAMPLE – PUSH-BUTTON CONTROL

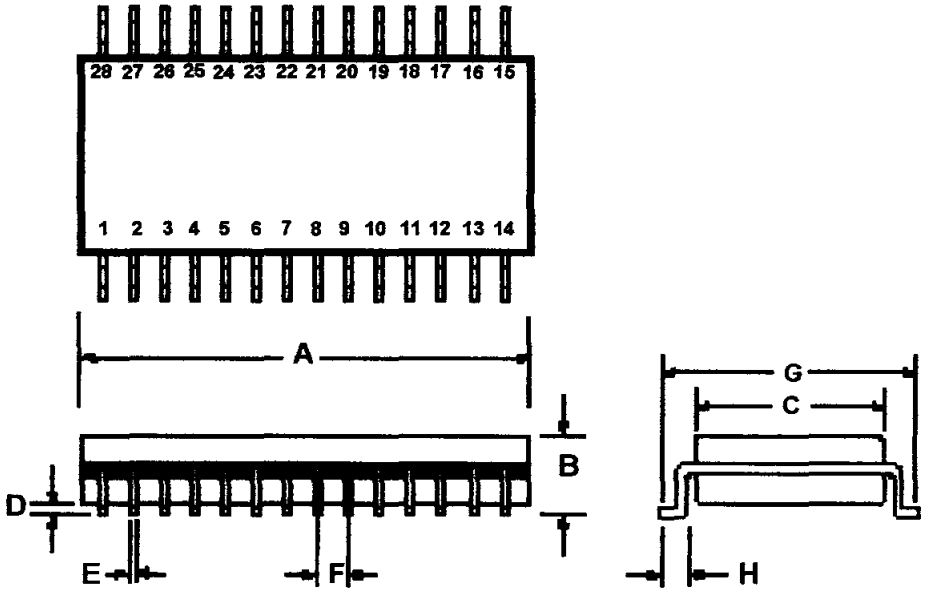
Control Step	Function	Action
1	Select Record/Playback Mode	P/$\overline{R}$ = As desired
2A	Begin playback	P/$\overline{R}$ = HIGH, $\overline{CE}$ = Pulse LOW
2B	Begin record	P/$\overline{R}$ = LOW, $\overline{CE}$ = Pulse LOW
3	Pause record or playback	$\overline{CE}$ = Pulsed LOW
4A	End playback	Automatic at $\overline{EOM}$ marker or PD = Pulsed HIGH
4B	End record	PD = Pulsed HIGH

TABLE 16: APPLICATION EXAMPLE – PASSIVE COMPONENT FUNCTIONS

Part	Function	Comments
R2	Release time constant	Sets release time for AGC
R4	Series limiting resistor	Reduces level to prevent distortion at higher supply voltages
R6, R7	Pull-up and pull-down resistors	Defines static state of inputs
C1, C4, C5	Power supply capacitors	Filters and bypass of power supply
C2	Attack/Release time constant	Sets attack/release time for AGC
C3	Low-frequency cutoff capacitor	Provides additional pole for low-frequency cutoff

12. PACKAGE DRAWING AND DIMENSIONS

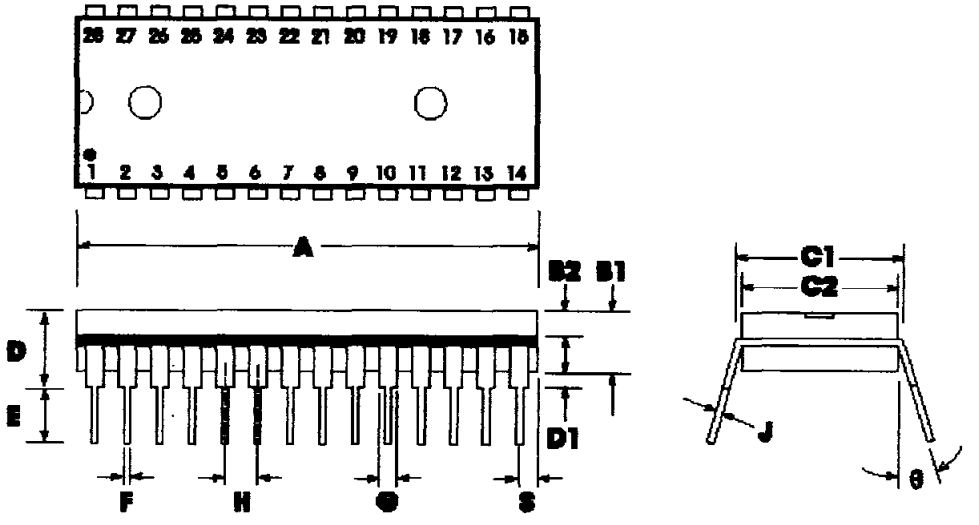
12.1. 28-LEAD 300-MIL PLASTIC SMALL OUTLINE IC (SOIC)



	INCHES			MILLIMETERS		
	Min	Nom	Max	Min	Nom	Max
A	0.701	0.706	0.711	17.81	17.93	18.06
B	0.097	0.101	0.104	2.46	2.56	2.64
C	0.292	0.296	0.299	7.42	7.52	7.59
D	0.005	0.009	0.0115	0.127	0.22	0.29
E	0.014	0.016	0.019	0.35	0.41	0.48
F		0.050			1.27	
G	0.400	0.406	0.410	10.16	10.31	10.41
H	0.024	0.032	0.040	0.61	0.81	1.02

Note: Lead coplanarity to be within 0.004 inches.

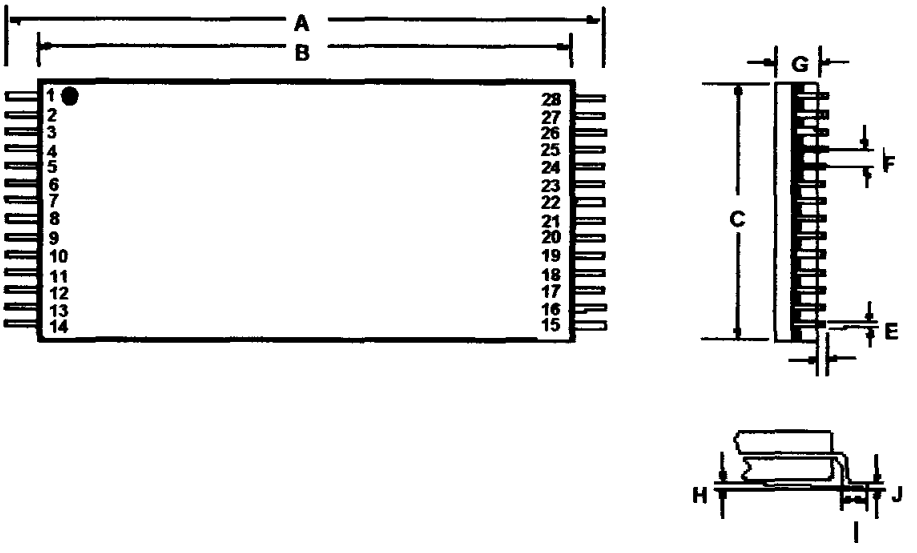
12.2. 28-LEAD 600-MIL PLASTIC DUAL INLINE PACKAGE (PDIP)



	INCHES			MILLIMETERS		
	Min	Nom	Max	Min	Nom	Max
A	1.445	1.450	1.455	36.70	36.83	36.96
B1		0.150			3.81	
B2	0.065	0.070	0.075	1.65	1.78	1.91
C1	0.600		0.625	15.24		15.88
C2	0.530	0.540	0.550	13.46	13.72	13.97
D			0.19			4.83
D1	0.015			0.38		
E	0.125		0.135	3.18		3.43
F	0.015	0.018	0.022	0.38	0.46	0.56
G	0.055	0.060	0.065	1.40	1.52	1.62
H		0.100			2.54	
J	0.008	0.010	0.012	0.20	0.25	0.30
S	0.070	0.075	0.080	1.78	1.91	2.03
q	0°		15°	0°		15°

Winbond Electronics Corp.

12.3. 28-LEAD 8X13.4MM PLASTIC THIN SMALL OUTLINE PACKAGE (TSOP) TYPE 1



Plastic Thin Small Outline Package (TSOP) Type 1 Dimensions

	INCHES			MILLIMETERS		
	Min	Nom	Max	Min	Nom	Max
A	0.520	0.528	0.535	13.20	13.40	13.60
B	0.461	0.465	0.469	11.70	11.80	11.90
C	0.311	0.315	0.319	7.90	8.00	8.10
D	0.002		0.006	0.05		0.15
E	0.007	0.009	0.011	0.17	0.22	0.27
F		0.0217			0.55	
G	0.037	0.039	0.041	0.95	1.00	1.05
H	0^0	3^0	6^0	0^0	3^0	6^0
I	0.020	0.022	0.028	0.50	0.55	0.70
J	0.004		0.008	0.10		0.21

Note: *Lead coplanarity to be within 0.004 inches.*

Winbond Electronics Corp.

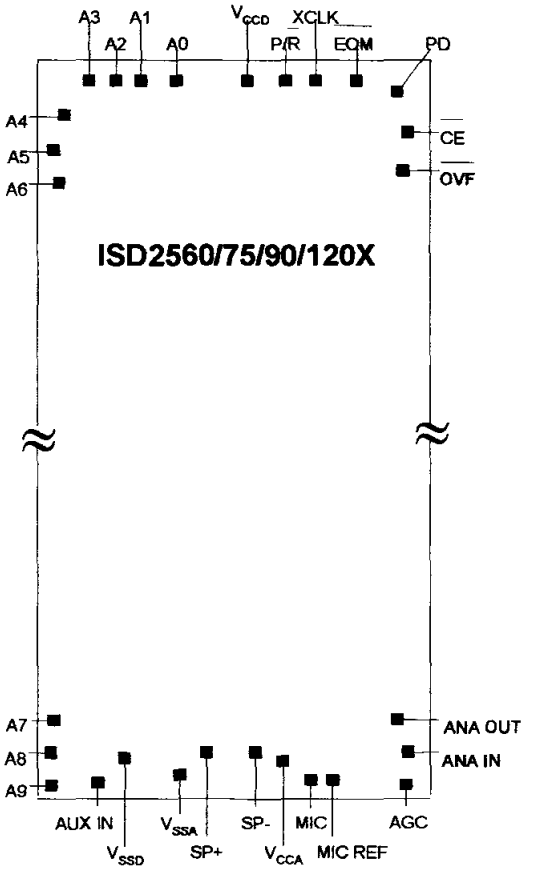
12.4. ISD2560/75/95/120 PRODUCT BONDING PHYSICAL LAYOUT (DIE) [1]

ISD2560/75/95/120

- Die Dimensions
  X: 149.5 ± 1 mils
  Y: 262.0 ± 1 mils

- Die Thickness [2]
  11.8 ± .4 mils

- Pad Opening
  111 x 111 microns
  4.4 x 4.4 mils



Notes:

[1] The backside of die is internally connected to V_{SS}. It **MUST NOT** be connected to any other potential or damage may occur.

[2] Die thickness is subject to change, please contact Winbond factory for status and availability.

Winbond Electronics Corp.

ISD2560/75/90/120 PRODUCT PAD DESIGNATIONS

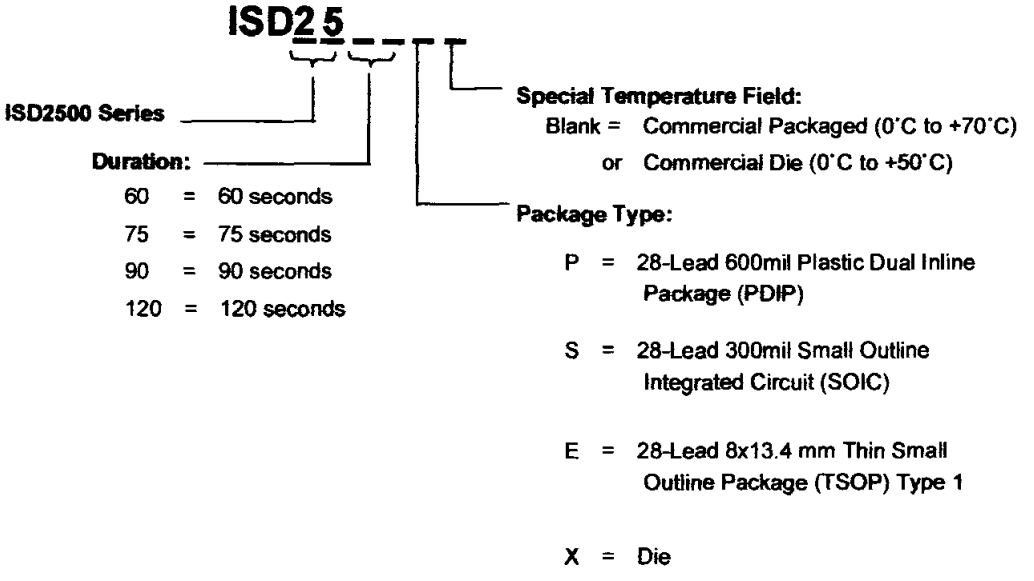
(with respect to die center)

Pad	Pad Name	X Axis (μm)	Y Axis (μm)
A0	Address 0	-897.9	3135.2
A1	Address 1	-1115.4	3135.2
A2	Address 2	-1331.0	3135.2
A3	Address 3	-1544.0	3135.2
A4	Address 4	-1640.4	2888.9
A5	Address 5	-1698.2	2671.0
A6	Address 6	-1698.2	2441.5
A7	Address 7	-1731.2	-2583.2
A8	Address 8	-1731.2	-2768.4
A9	Address 9	-1731.2	-3050.8
AUX IN	Auxiliary Input	-1410.2	-3115.7
V_{SSD}	V_{SS} Digital Power Supply	-1112.4	-3096.5
V_{SSA}	V_{SS} Analog Power Supply	-408.2	-3138.9
SP+	Speaker Output +	-46.65	-3068.4
SP-	Speaker Output -	386.1	-3068.4
V_{CCA}	V_{CC} Analog Power Supply	746.9	-3110.8
MIC	Microphone Input	1101.2	-3146.0
MIC REF	Microphone Reference	1294.7	-3146.0
AGC	Automatic Gain Control	1666.4	-3130.3
ANA IN	Analog Input	1728.6	-2654.0
ANA OUT	Analog Output	1700.9	-2411.0
$\overline{OVF}$	Overflow Output	1674.6	2489.5
$\overline{CE}$	Chip Enable Input	1726.7	2824.4
PD	Power Down Input	1730.5	3094.0
$\overline{EOM}$	End of Message	1341.2	3122.1
XCLK	No Connect (optional)	986.5	3160.7
$P/\overline{R}$	Playback/Record	807.2	3163.4
V_{CCD}	V_{CC} Digital Power Supply	544.4	3159.6

Winbond Electronics Corp.

13. ORDERING INFORMATION

Product Number Descriptor Key



When ordering ISD2560/75/90/120 products refer to the following part numbers which are supported in volume for this product series. Consult the local Winbond Sales Representative or Distributor for availability information.

Part Number	Part Number	Part Number	Part Number
ISD2560P	ISD2575P	ISD2590P	ISD25120P
ISD2560S	ISD2575S	ISD2590S	ISD25120S
ISD2560E	ISD2575E	ISD2590E	
ISD2560X	ISD2575X	ISD2590X	ISD25120X

For the latest product information, access Winbond's worldwide website at http://www.winbond-usa.com

14. VERSION HISTORY

VERSION	DATE	PAGE	DESCRIPTION
0	Apr. 1998	All	Preliminary Specifications
1.0	May 2003	All	Re-format the document. Update TSOP pin configuration. Revise Overflow pad designation.

Winbond Electronics Corp.

The contents of this document are provided only as a guide for the applications of Winbond products. Winbond makes no representation or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to discontinue or make changes to specifications and product descriptions at any time without notice. No license, whether express or implied, to any intellectual property or other right of Winbond or others is granted by this publication. Except as set forth in Winbond's Standard Terms and Conditions of Sale, Winbond assumes no liability whatsoever and disclaims any express or implied warranty of merchantability, fitness for a particular purpose or infringement of any Intellectual property.

Winbond products are not designed, intended, authorized or warranted for use as components in systems or equipments intended for surgical implantation, atomic energy control instruments, airplane or spaceship instruments, transportation instruments, traffic signal instruments, combustion control instruments, or for other applications intended to support or sustain life. Further more, Winbond products are not intended for applications wherein failure of Winbond products could result or lead to a situation wherein personal injury, death or severe property or environmental injury could occur.

Application examples and alternative uses of any integrated circuit contained in this publication are for illustration only and Winbond makes no representation or warranty that such applications shall be suitable for the use specified.

ISD® and ChipCorder® are trademarks of Winbond Electronics Corporation.

The 100-year retention and 100K record cycle projections are based upon accelerated reliability tests, as published in the Winbond Reliability Report, and are neither warranted nor guaranteed by Winbond.

Information contained in this ISD® ChipCorder® data sheet supersedes all data for the ISD ChipCorder products published by ISD® prior to August, 1998.

This data sheet and any future addendum to this data sheet is(are) the complete and controlling ISD® ChipCorder® product specifications. In the event any inconsistencies exist between the information in this and other product documentation, or in the event that other product documentation contains information in addition to the information in this, the information contained herein supersedes and governs such other information in its entirety.

Winbond Electronics Corp.

Headquarters
No. 4, Creation Rd. III
Science-Based Industrial Park,
Hsinchu, Taiwan
TEL: 886-3-5770066
FAX: 886-3-5665577
http://www.winbond.com.tw/

Winbond Electronics Corporation America
2727 North First Street, San Jose,
CA 95134, U.S.A.
TEL: 1-408-9436666
FAX: 1-408-5441797
http://www.winbond-usa.com/

Winbond Electronics (Shanghai) Ltd.
27F, 299 Yan An W. Rd. Shanghai,
200336 China
TEL: 86-21-62365999
FAX: 86-21-62356998

Taipei Office
9F, No. 480, Pueiguang Rd.
Neihu District
Taipei, 114 Taiwan
TEL: 886-2-81777168
FAX: 886-2-87153579

Winbond Electronics Corporation Japan
7F Daini-ueno BLDG. 3-7-18
Shinyokohama Kohokuku,
Yokohama, 222-0033
TEL: 81-45-4781881
FAX: 81-45-4781800

Winbond Electronics (H.K.) Ltd.
Unit 9-15, 22F, Millennium City,
No. 378 Kwun Tong Rd.,
Kowloon, Hong Kong
TEL: 852-27513100
FAX: 852-27552064

Features

- Compatible with MCS®-51 Products
- 4K Bytes of In-System Programmable (ISP) Flash Memory
  - Endurance: 1000 Write/Erase Cycles
- 4.0V to 5.5V Operating Range
- Fully Static Operation: 0 Hz to 33 MHz
- Three-level Program Memory Lock
- 128 x 8-bit Internal RAM
- 32 Programmable I/O Lines
- Two 16-bit Timer/Counters
- Six Interrupt Sources
- Full Duplex UART Serial Channel
- Low-power Idle and Power-down Modes
- Interrupt Recovery from Power-down Mode
- Watchdog Timer
- Dual Data Pointer
- Power-off Flag
- Fast Programming Time
- Flexible ISP Programming (Byte and Page Mode)

Description

The AT89S51 is a low-power, high-performance CMOS 8-bit microcontroller with 4K bytes of In-System Programmable Flash memory. The device is manufactured using Atmel's high-density nonvolatile memory technology and is compatible with the industry-standard 80C51 instruction set and pinout. The on-chip Flash allows the program memory to be reprogrammed in-system or by a conventional nonvolatile memory programmer. By combining a versatile 8-bit CPU with In-System Programmable Flash on a monolithic chip, the Atmel AT89S51 is a powerful microcontroller which provides a highly-flexible and cost-effective solution to many embedded control applications.

The AT89S51 provides the following standard features: 4K bytes of Flash, 128 bytes of RAM, 32 I/O lines, Watchdog timer, two data pointers, two 16-bit timer/counters, a five-vector two-level interrupt architecture, a full duplex serial port, on-chip oscillator, and clock circuitry. In addition, the AT89S51 is designed with static logic for operation down to zero frequency and supports two software selectable power saving modes. The Idle Mode stops the CPU while allowing the RAM, timer/counters, serial port, and interrupt system to continue functioning. The Power-down mode saves the RAM contents but freezes the oscillator, disabling all other chip functions until the next external interrupt or hardware reset.

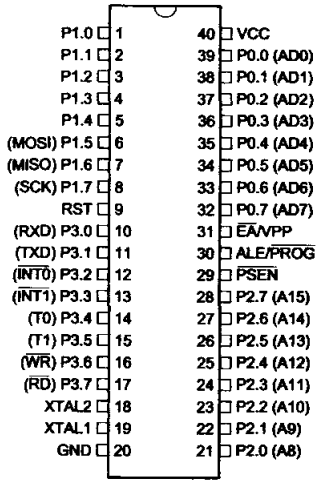
8-bit Microcontroller with 4K Bytes In-System Programmable Flash

AT89S51

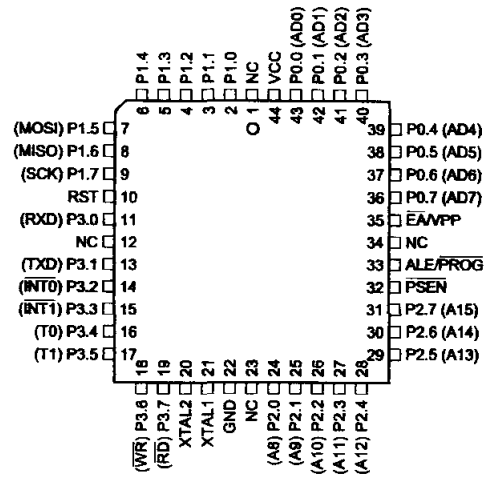
2487B–MICRO–12/03

Pin Configurations

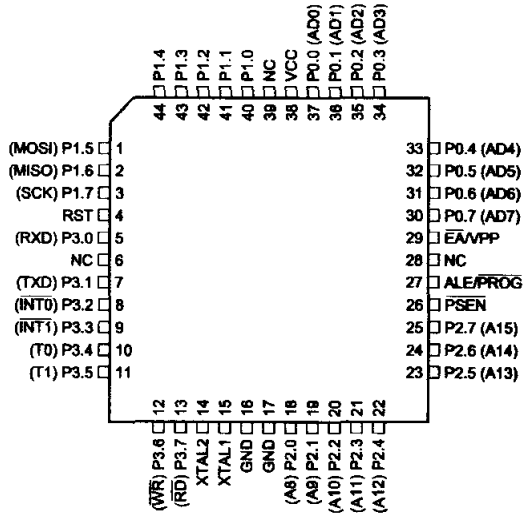
PDIP



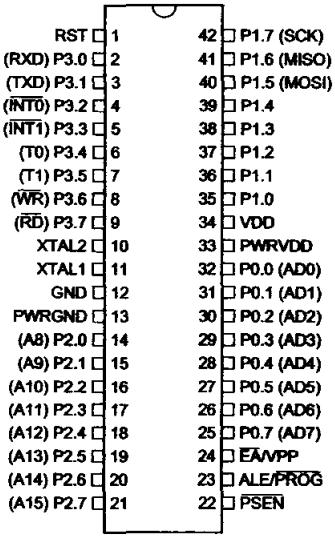
PLCC



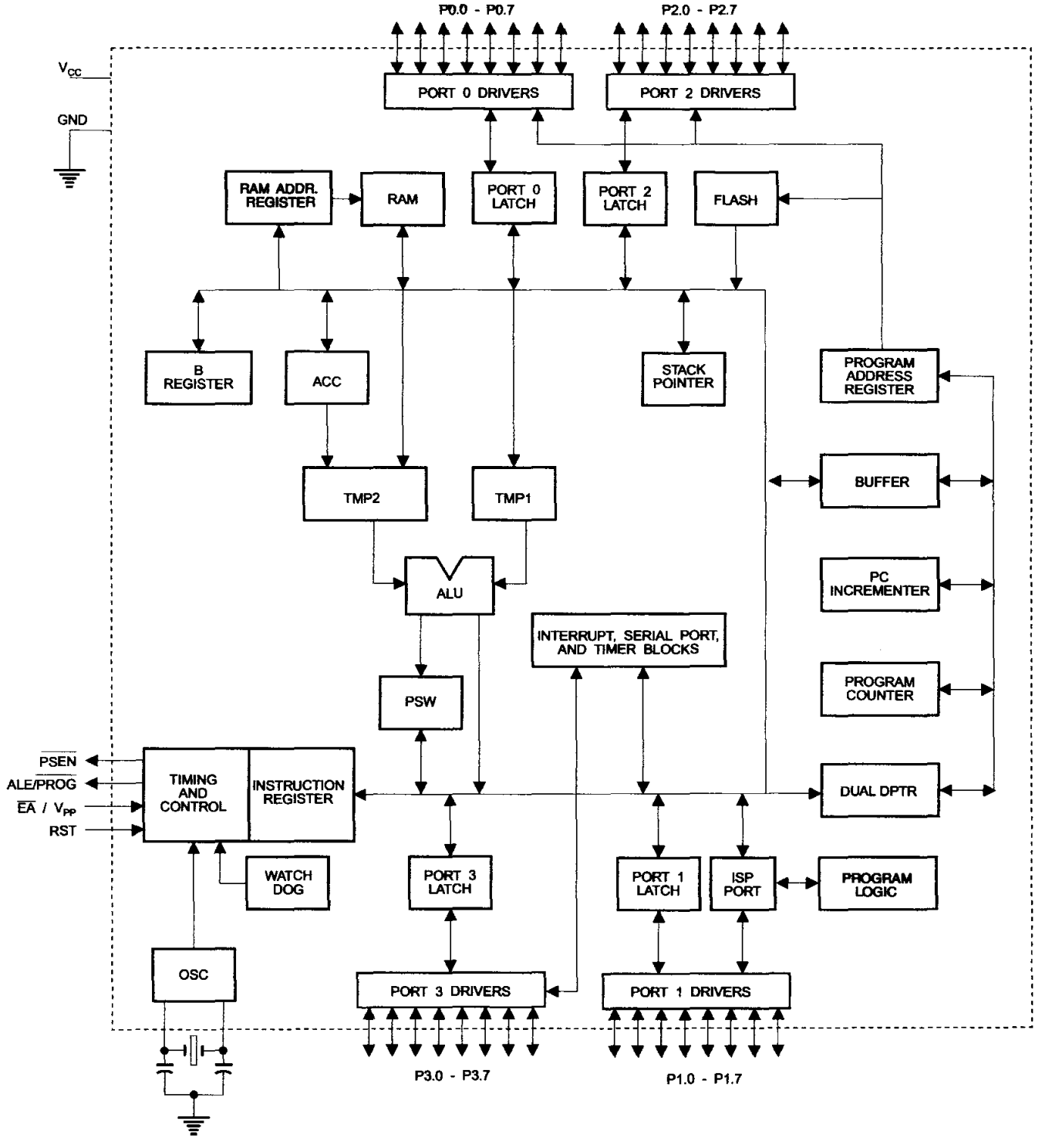
TQFP



PDIP



Block Diagram



Pin Description

VCC

Supply voltage (all packages except 42-PDIP).

GND

Ground (all packages except 42-PDIP; for 42-PDIP GND connects only the logic core and the embedded program memory).

VDD

Supply voltage for the 42-PDIP which connects only the logic core and the embedded program memory.

PWRVDD

Supply voltage for the 42-PDIP which connects only the I/O Pad Drivers. The application board **MUST** connect both VDD and PWRVDD to the board supply voltage.

PWRGND

Ground for the 42-PDIP which connects only the I/O Pad Drivers. PWRGND and GND are weakly connected through the common silicon substrate, but not through any metal link. The application board **MUST** connect both GND and PWRGND to the board ground.

Port 0

Port 0 is an 8-bit open drain bi-directional I/O port. As an output port, each pin can sink eight TTL inputs. When 1s are written to port 0 pins, the pins can be used as high-impedance inputs.

Port 0 can also be configured to be the multiplexed low-order address/data bus during accesses to external program and data memory. In this mode, P0 has internal pull-ups.

Port 0 also receives the code bytes during Flash programming and outputs the code bytes during program verification. **External pull-ups are required during program verification.**

Port 1

Port 1 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 1 output buffers can sink/source four TTL inputs. When 1s are written to Port 1 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 1 also receives the low-order address bytes during Flash programming and verification.

Port Pin	Alternate Functions
P1.5	MOSI (used for In-System Programming)
P1.6	MISO (used for In-System Programming)
P1.7	SCK (used for In-System Programming)

Port 2

Port 2 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four TTL inputs. When 1s are written to Port 2 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally being pulled low will source current (I_{IL}) because of the internal pull-ups.

Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX @ DPTR). In this application, Port 2 uses strong internal pull-ups when emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX @ RI), Port 2 emits the contents of the P2 Special Function Register.

Port 2 also receives the high-order address bits and some control signals during Flash programming and verification.

Port 3

Port 3 is an 8-bit bi-directional I/O port with internal pull-ups. The Port 3 output buffers can sink/source four TTL inputs. When 1s are written to Port 3 pins, they are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally being pulled low will source current (I_{IL}) because of the pull-ups.

Port 3 receives some control signals for Flash programming and verification.

Port 3 also serves the functions of various special features of the AT89S51, as shown in the following table.

Port Pin	Alternate Functions
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	$\overline{INT0}$ (external interrupt 0)
P3.3	$\overline{INT1}$ (external interrupt 1)
P3.4	T0 (timer 0 external input)
P3.5	T1 (timer 1 external input)
P3.6	$\overline{WR}$ (external data memory write strobe)
P3.7	$\overline{RD}$ (external data memory read strobe)

RST

Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device. This pin drives High for 98 oscillator periods after the Watchdog times out. The DISRTO bit in SFR AUXR (address 8EH) can be used to disable this feature. In the default state of bit DISRTO, the RESET HIGH out feature is enabled.

ALE/$\overline{PROG}$

Address Latch Enable (ALE) is an output pulse for latching the low byte of the address during accesses to external memory. This pin is also the program pulse input ($\overline{PROG}$) during Flash programming.

In normal operation, ALE is emitted at a constant rate of 1/6 the oscillator frequency and may be used for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external data memory.

If desired, ALE operation can be disabled by setting bit 0 of SFR location 8EH. With the bit set, ALE is active only during a MOVX or MOVC instruction. Otherwise, the pin is weakly pulled high. Setting the ALE-disable bit has no effect if the microcontroller is in external execution mode.

$\overline{PSEN}$

Program Store Enable ($\overline{PSEN}$) is the read strobe to external program memory.

When the AT89S51 is executing code from external program memory, $\overline{PSEN}$ is activated twice each machine cycle, except that two $\overline{PSEN}$ activations are skipped during each access to external data memory.

$\overline{EA}$/VPP

External Access Enable. $\overline{EA}$ must be strapped to GND in order to enable the device to fetch code from external program memory locations starting at 0000H up to FFFFH. Note, however, that if lock bit 1 is programmed, $\overline{EA}$ will be internally latched on reset.

$\overline{EA}$ should be strapped to V_{CC} for internal program executions.

This pin also receives the 12-volt programming enable voltage (V_{PP}) during Flash programming.

XTAL1

Input to the inverting oscillator amplifier and input to the internal clock operating circuit.

XTAL2

Output from the inverting oscillator amplifier

Special Function Registers

A map of the on-chip memory area called the Special Function Register (SFR) space is shown in Table 1.

Note that not all of the addresses are occupied, and unoccupied addresses may not be implemented on the chip. Read accesses to these addresses will in general return random data, and write accesses will have an indeterminate effect.

Table 1. AT89S51 SFR Map and Reset Values

0F8H								0FFH
0F0H	B 00000000							0F7H
0E8H								0EFH
0E0H	ACC 00000000							0E7H
0D8H								0DFH
0D0H	PSW 00000000							0D7H
0C8H								0CFH
0C0H								0C7H
0B8H	IP XX000000							0BFH
0B0H	P3 11111111							0B7H
0A8H	IE 0X000000							0AFH
0A0H	P2 11111111		AUXR1 XXXXXXX0				WDTRST XXXXXXXX		0A7H
98H	SCON 00000000	SBUF XXXXXXXX							9FH
90H	P1 11111111								97H
88H	TCON 00000000	TMOD 00000000	TL0 00000000	TL1 00000000	TH0 00000000	TH1 00000000	AUXR XXX00XX0		8FH
80H	P0 11111111	SP 00000111	DP0L 00000000	DP0H 00000000	DP1L 00000000	DP1H 00000000		PCON 0XXX0000	87H

User software should not write 1s to these unlisted locations, since they may be used in future products to invoke new features. In that case, the reset or inactive values of the new bits will always be 0.

Interrupt Registers: The individual interrupt enable bits are in the IE register. Two priorities can be set for each of the five interrupt sources in the IP register.

Table 2. AUXR: Auxiliary Register

AUXR Address = 8EH Reset Value = XXX00XX0B

Not Bit Addressable

	–	–	–	WDIDLE	DISRTO	–	–	DISALE
Bit	7	6	5	4	3	2	1	0

–	Reserved for future expansion
DISALE	Disable/Enable ALE
	DISALE Operating Mode
	0 ALE is emitted at a constant rate of 1/6 the oscillator frequency
	1 ALE is active only during a MOVX or MOVC instruction
DISRTO	Disable/Enable Reset-out
	DISRTO
	0 Reset pin is driven High after WDT times out
	1 Reset pin is input only
WDIDLE	Disable/Enable WDT in IDLE mode
WDIDLE	
0	WDT continues to count in IDLE mode
1	WDT halts counting in IDLE mode

Dual Data Pointer Registers: To facilitate accessing both internal and external data memory, two banks of 16-bit Data Pointer Registers are provided: DP0 at SFR address locations 82H-83H and DP1 at 84H-85H. Bit DPS = 0 in SFR AUXR1 selects DP0 and DPS = 1 selects DP1. The user should **ALWAYS** initialize the DPS bit to the appropriate value before accessing the respective Data Pointer Register.

Power Off Flag: The Power Off Flag (POF) is located at bit 4 (PCON.4) in the PCON SFR. POF is set to "1" during power up. It can be set and rest under software control and is not affected by reset.

Table 3. AUXR1: Auxiliary Register 1

AUXR1 Address = A2H Reset Value = XXXXXXX0B

Not Bit Addressable

	–	–	–	–	–	–	–	DPS
Bit	7	6	5	4	3	2	1	0

– Reserved for future expansion

DPS Data Pointer Register Select

DPS	
0	Selects DPTR Registers DP0L, DP0H
1	Selects DPTR Registers DP1L, DP1H

Memory Organization

MCS-51 devices have a separate address space for Program and Data Memory. Up to 64K bytes each of external Program and Data Memory can be addressed.

Program Memory

If the $\overline{EA}$ pin is connected to GND, all program fetches are directed to external memory.

On the AT89S51, if $\overline{EA}$ is connected to V_{CC}, program fetches to addresses 0000H through FFFH are directed to internal memory and fetches to addresses 1000H through FFFFH are directed to external memory.

Data Memory

The AT89S51 implements 128 bytes of on-chip RAM. The 128 bytes are accessible via direct and indirect addressing modes. Stack operations are examples of indirect addressing, so the 128 bytes of data RAM are available as stack space.

Watchdog Timer (One-time Enabled with Reset-out)

The WDT is intended as a recovery method in situations where the CPU may be subjected to software upsets. The WDT consists of a 14-bit counter and the Watchdog Timer Reset (WDTRST) SFR. The WDT is defaulted to disable from exiting reset. To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, it will increment every machine cycle while the oscillator is running. The WDT timeout period is dependent on the external clock frequency. There is no way to disable the WDT except through reset (either hardware reset or WDT overflow reset). When WDT overflows, it will drive an output RESET HIGH pulse at the RST pin.

Using the WDT

To enable the WDT, a user must write 01EH and 0E1H in sequence to the WDTRST register (SFR location 0A6H). When the WDT is enabled, the user needs to service it by writing 01EH and 0E1H to WDTRST to avoid a WDT overflow. The 14-bit counter overflows when it reaches 16383 (3FFFH), and this will reset the device. When the WDT is enabled, it will increment every machine cycle while the oscillator is running. This means the user must reset the WDT at least every 16383 machine cycles. To reset the WDT the user must write 01EH and 0E1H to WDTRST. WDTRST is a write-only register. The WDT counter cannot be read or written. When WDT overflows, it will generate an output RESET pulse at the RST pin. The RESET pulse duration is 98xTOSC, where TOSC = 1/FOSC. To make the best use of the WDT, it should be serviced in those sections of code that will periodically be executed within the time required to prevent a WDT reset.

WDT During Power-down and Idle

In Power-down mode the oscillator stops, which means the WDT also stops. While in Power-down mode, the user does not need to service the WDT. There are two methods of exiting Power-down mode: by a hardware reset or via a level-activated external interrupt, which is enabled prior to entering Power-down mode. When Power-down is exited with hardware reset, servicing the WDT should occur as it normally does whenever the AT89S51 is reset. Exiting Power-down with an interrupt is significantly different. The interrupt is held low long enough for the oscillator to stabilize. When the interrupt is brought high, the interrupt is serviced. To prevent the WDT from resetting the device while the interrupt pin is held low, the WDT is not started until the interrupt is pulled high. It is suggested that the WDT be reset during the interrupt service for the interrupt used to exit Power-down mode.

To ensure that the WDT does not overflow within a few states of exiting Power-down, it is best to reset the WDT just before entering Power-down mode.

Before going into the IDLE mode, the WDIDLE bit in SFR AUXR is used to determine whether the WDT continues to count if enabled. The WDT keeps counting during IDLE (WDIDLE bit = 0) as the default state. To prevent the WDT from resetting the AT89S51 while in IDLE mode, the user should always set up a timer that will periodically exit IDLE, service the WDT, and reenter IDLE mode.

With WDIDLE bit enabled, the WDT will stop to count in IDLE mode and resumes the count upon exit from IDLE.

UART

The UART in the AT89S51 operates the same way as the UART in the AT89C51. For further information on the UART operation, refer to the Atmel Web site (http://www.atmel.com). From the home page, select "Products", then "Microcontrollers", then "8051-Architecture", then "Documentation", and "Other Documents". Open the Adobe® Acrobat® file "AT89 Series Hardware Description".

Timer 0 and 1

Timer 0 and Timer 1 in the AT89S51 operate the same way as Timer 0 and Timer 1 in the AT89C51. For further information on the timers' operation, refer to the Atmel Web site (http://www.atmel.com). From the home page, select "Products", then "Microcontrollers", then "8051-Architecture", then "Documentation", and "Other Documents". Open the Adobe Acrobat file "AT89 Series Hardware Description".

Interrupts

The AT89S51 has a total of five interrupt vectors: two external interrupts ($\overline{INT0}$ and $\overline{INT1}$), two timer interrupts (Timers 0 and 1), and the serial port interrupt. These interrupts are all shown in Figure 1.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE. IE also contains a global disable bit, EA, which disables all interrupts at once.

Note that Table 4 shows that bit positions IE.6 and IE.5 are unimplemented. User software should not write 1s to these bit positions, since they may be used in future AT89 products.

The Timer 0 and Timer 1 flags, TF0 and TF1, are set at S5P2 of the cycle in which the timers overflow. The values are then polled by the circuitry in the next cycle.

Table 4. Interrupt Enable (IE) Register

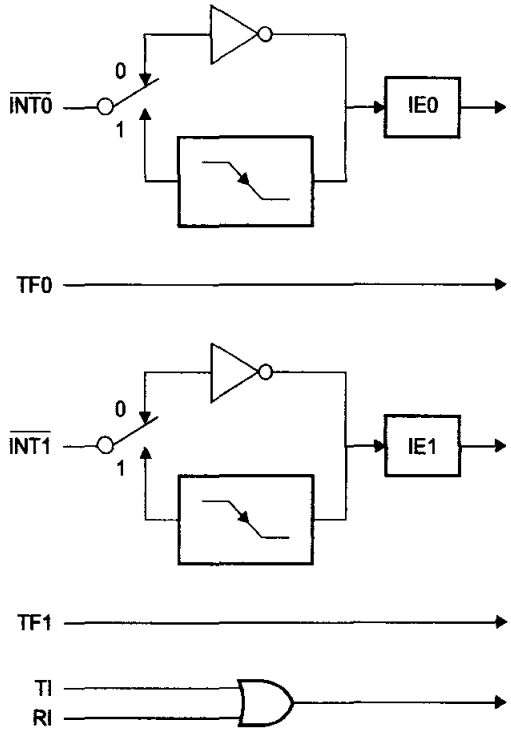
(MSB)							(LSB)
EA	–	–	ES	ET1	EX1	ET0	EX0

Enable Bit = 1 enables the interrupt.

Enable Bit = 0 disables the interrupt.

Symbol	Position	Function
EA	IE.7	Disables all interrupts. If EA = 0, no interrupt is acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
–	IE.6	Reserved
–	IE.5	Reserved
ES	IE.4	Serial Port interrupt enable bit
ET1	IE.3	Timer 1 interrupt enable bit
EX1	IE.2	External interrupt 1 enable bit
ET0	IE.1	Timer 0 interrupt enable bit
EX0	IE.0	External interrupt 0 enable bit
User software should never write 1s to reserved bits, because they may be used in future AT89 products.		

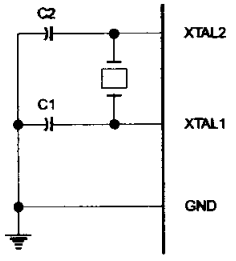
Figure 1. Interrupt Sources



Oscillator Characteristics

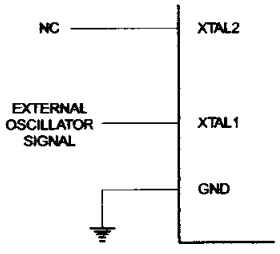
XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier that can be configured for use as an on-chip oscillator, as shown in Figure 2. Either a quartz crystal or ceramic resonator may be used. To drive the device from an external clock source, XTAL2 should be left unconnected while XTAL1 is driven, as shown in Figure 3. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum voltage high and low time specifications must be observed.

Figure 2. Oscillator Connections



Note: C1, C2 = 30 pF ± 10 pF for Crystals
= 40 pF ± 10 pF for Ceramic Resonators

Figure 3. External Clock Drive Configuration



Idle Mode

In idle mode, the CPU puts itself to sleep while all the on-chip peripherals remain active. The mode is invoked by software. The content of the on-chip RAM and all the special function registers remain unchanged during this mode. The idle mode can be terminated by any enabled interrupt or by a hardware reset.

Note that when idle mode is terminated by a hardware reset, the device normally resumes program execution from where it left off, up to two machine cycles before the internal reset algorithm takes control. On-chip hardware inhibits access to internal RAM in this event, but access to the port pins is not inhibited. To eliminate the possibility of an unexpected write to a port pin when idle mode is terminated by a reset, the instruction following the one that invokes idle mode should not write to a port pin or to external memory.

Power-down Mode

In the Power-down mode, the oscillator is stopped, and the instruction that invokes Power-down is the last instruction executed. The on-chip RAM and Special Function Registers retain their values until the Power-down mode is terminated. Exit from Power-down mode can be initiated either by a hardware reset or by activation of an enabled external interrupt ($\overline{INT0}$ or $\overline{INT1}$). Reset redefines the SFRs but does not change the on-chip RAM. The reset should not be activated before V_{CC} is restored to its normal operating level and must be held active long enough to allow the oscillator to restart and stabilize.

Table 5. Status of External Pins During Idle and Power-down Modes

Mode	Program Memory	ALE	$\overline{PSEN}$	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Data	Data	Data	Data
Idle	External	1	1	Float	Data	Address	Data
Power-down	Internal	0	0	Data	Data	Data	Data
Power-down	External	0	0	Float	Data	Data	Data

Program Memory Lock Bits

The AT89S51 has three lock bits that can be left unprogrammed (U) or can be programmed (P) to obtain the additional features listed in the following table.

Table 6. Lock Bit Protection Modes

Program Lock Bits				
	LB1	LB2	LB3	Protection Type
1	U	U	U	No program lock features
2	P	U	U	MOVC instructions executed from external program memory are disabled from fetching code bytes from internal memory, $\overline{EA}$ is sampled and latched on reset, and further programming of the Flash memory is disabled
3	P	P	U	Same as mode 2, but verify is also disabled
4	P	P	P	Same as mode 3, but external execution is also disabled

When lock bit 1 is programmed, the logic level at the $\overline{EA}$ pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value and holds that value until reset is activated. The latched value of $\overline{EA}$ must agree with the current logic level at that pin in order for the device to function properly.

Programming the Flash – Parallel Mode

The AT89S51 is shipped with the on-chip Flash memory array ready to be programmed. The programming interface needs a high-voltage (12-volt) program enable signal and is compatible with conventional third-party Flash or EPROM programmers.

The AT89S51 code memory array is programmed byte-by-byte.

Programming Algorithm: Before programming the AT89S51, the address, data, and control signals should be set up according to the Flash Programming Modes table (Table 7) and Figures 4 and 5. To program the AT89S51, take the following steps:

1. Input the desired memory location on the address lines.
2. Input the appropriate data byte on the data lines.
3. Activate the correct combination of control signals.
4. Raise $\overline{EA}/V_{PP}$ to 12V.
5. Pulse ALE/$\overline{PROG}$ once to program a byte in the Flash array or the lock bits. The byte-write cycle is self-timed and typically takes no more than 50 µs. Repeat steps 1 through 5, changing the address and data for the entire array or until the end of the object file is reached.

$\overline{Data}$ Polling: The AT89S51 features $\overline{Data}$ Polling to indicate the end of a byte write cycle. During a write cycle, an attempted read of the last byte written will result in the complement of the written data on P0.7. Once the write cycle has been completed, true data is valid on all outputs, and the next cycle may begin. $\overline{Data}$ Polling may begin any time after a write cycle has been initiated.

Ready/Busy: The progress of byte programming can also be monitored by the RDY/$\overline{BSY}$ output signal. P3.0 is pulled low after ALE goes high during programming to indicate $\overline{BUSY}$. P3.0 is pulled high again when programming is done to indicate READY.

Program Verify: If lock bits LB1 and LB2 have not been programmed, the programmed code data can be read back via the address and data lines for verification. **The status of the individual lock bits can be verified directly by reading them back.**

Reading the Signature Bytes: The signature bytes are read by the same procedure as a normal verification of locations 000H, 100H, and 200H, except that P3.6 and P3.7 must be pulled to a logic low. The values returned are as follows.

(000H) = 1EH indicates manufactured by Atmel
(100H) = 51H indicates AT89S51
(200H) = 06H

Chip Erase: In the parallel programming mode, a chip erase operation is initiated by using the proper combination of control signals and by pulsing ALE/$\overline{PROG}$ low for a duration of 200 ns - 500 ns.

In the serial programming mode, a chip erase operation is initiated by issuing the Chip Erase instruction. In this mode, chip erase is self-timed and takes about 500 ms.

During chip erase, a serial read from any address location will return 00H at the data output.

Programming the Flash – Serial Mode

The Code memory array can be programmed using the serial ISP interface while RST is pulled to V_{CC}. The serial interface consists of pins SCK, MOSI (input) and MISO (output). After RST is set high, the Programming Enable instruction needs to be executed first before other operations can be executed. Before a reprogramming sequence can occur, a Chip Erase operation is required.

The Chip Erase operation turns the content of every memory location in the Code array into FFH.

Either an external system clock can be supplied at pin XTAL1 or a crystal needs to be connected across pins XTAL1 and XTAL2. The maximum serial clock (SCK) frequency should be less than 1/16 of the crystal frequency. With a 33 MHz oscillator clock, the maximum SCK frequency is 2 MHz.

Serial Programming Algorithm

To program and verify the AT89S51 in the serial programming mode, the following sequence is recommended:

1. Power-up sequence:
   Apply power between VCC and GND pins.
   Set RST pin to "H".
   If a crystal is not connected across pins XTAL1 and XTAL2, apply a 3 MHz to 33 MHz clock to XTAL1 pin and wait for at least 10 milliseconds.
2. Enable serial programming by sending the Programming Enable serial instruction to pin MOSI/P1.5. The frequency of the shift clock supplied at pin SCK/P1.7 needs to be less than the CPU clock at XTAL1 divided by 16.
3. The Code array is programmed one byte at a time in either the Byte or Page mode. The write cycle is self-timed and typically takes less than 0.5 ms at 5V.
4. Any memory location can be verified by using the Read instruction that returns the content at the selected address at serial output MISO/P1.6.
5. At the end of a programming session, RST can be set low to commence normal device operation.

Power-off sequence (if needed):

Set XTAL1 to "L" (if a crystal is not used).

Set RST to "L".

Turn V_{CC} power off.

Data Polling: The Data Polling feature is also available in the serial mode. In this mode, during a write cycle an attempted read of the last byte written will result in the complement of the MSB of the serial output byte on MISO.

Serial Programming Instruction Set

The Instruction Set for Serial Programming follows a 4-byte protocol and is shown in Table 8.

Programming Interface – Parallel Mode

Every code byte in the Flash array can be programmed by using the appropriate combination of control signals. The write operation cycle is self-timed and once initiated, will automatically time itself to completion.

Most major worldwide programming vendors offer worldwide support for the Atmel AT89 microcontroller series. Please contact your local programming vendor for the appropriate software revision.

Table 7. Flash Programming Modes

Mode	V_{CC}	RST	PSEN	ALE/PROG	EA/V_{PP}	P2.6	P2.7	P3.3	P3.6	P3.7	P0.7-0 Data	P2.3-0 Address	P1.7-0 Address
Write Code Data	5V	H	L	(2)	12V	L	H	H	H	H	D_{IN}	A11-8	A7-0
Read Code Data	5V	H	L	H	H	L	L	L	H	H	D_{OUT}	A11-8	A7-0
Write Lock Bit 1	5V	H	L	(3)	12V	H	H	H	H	H	X	X	X
Write Lock Bit 2	5V	H	L	(3)	12V	H	H	H	L	L	X	X	X
Write Lock Bit 3	5V	H	L	(3)	12V	H	L	H	H	L	X	X	X
Read Lock Bits 1, 2, 3	5V	H	L	H	H	H	H	L	H	L	P0.2, P0.3, P0.4	X	X
Chip Erase	5V	H	L	(1)	12V	H	L	H	L	L	X	X	X
Read Atmel ID	5V	H	L	H	H	L	L	L	L	L	1EH	0000	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	51H	0001	00H
Read Device ID	5V	H	L	H	H	L	L	L	L	L	06H	0010	00H

Notes:
1. Each PROG pulse is 200 ns - 500 ns for Chip Erase.
2. Each PROG pulse is 200 ns - 500 ns for Write Code Data.
3. Each PROG pulse is 200 ns - 500 ns for Write Lock Bits.
4. RDY/BSY signal is output on P3.0 during programming.
5. X = don't care.

Figure 4. Programming the Flash Memory (Parallel Mode)

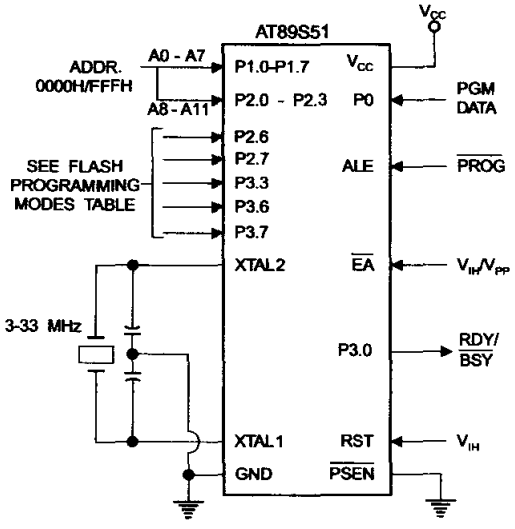
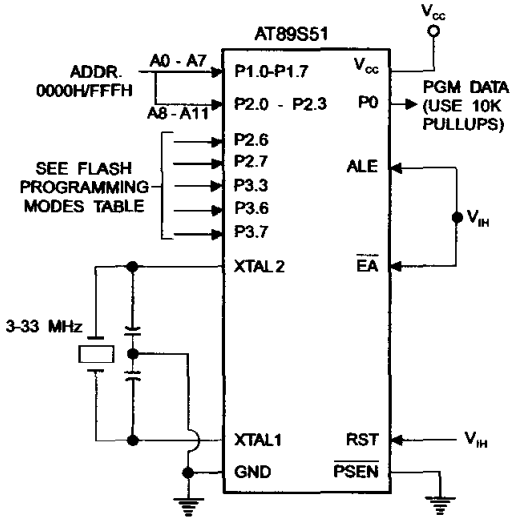


Figure 5. Verifying the Flash Memory (Parallel Mode)



Flash Programming and Verification Characteristics (Parallel Mode)

T_A = 20°C to 30°C, V_{CC} = 4.5 to 5.5V

Symbol	Parameter	Min	Max	Units
V_{PP}	Programming Supply Voltage	11.5	12.5	V
I_{PP}	Programming Supply Current		10	mA
I_{CC}	V_{CC} Supply Current		30	mA
$1/t_{CLCL}$	Oscillator Frequency	3	33	MHz
t_{AVGL}	Address Setup to $\overline{PROG}$ Low	$48t_{CLCL}$		
t_{GHAX}	Address Hold After $\overline{PROG}$	$48t_{CLCL}$		
t_{DVGL}	Data Setup to $\overline{PROG}$ Low	$48t_{CLCL}$		
t_{GHDX}	Data Hold After $\overline{PROG}$	$48t_{CLCL}$		
t_{EHSH}	P2.7 ($\overline{ENABLE}$) High to V_{PP}	$48t_{CLCL}$		
t_{SHGL}	V_{PP} Setup to $\overline{PROG}$ Low	10		µs
t_{GHSL}	V_{PP} Hold After $\overline{PROG}$	10		µs
t_{GLGH}	$\overline{PROG}$ Width	0.2	1	µs
t_{AVQV}	Address to Data Valid		$48t_{CLCL}$	
t_{ELQV}	$\overline{ENABLE}$ Low to Data Valid		$48t_{CLCL}$	
t_{EHQZ}	Data Float After $\overline{ENABLE}$	0	$48t_{CLCL}$	
t_{GHBL}	$\overline{PROG}$ High to $\overline{BUSY}$ Low		1.0	µs
t_{WC}	Byte Write Cycle Time		50	µs

Figure 6. Flash Programming and Verification Waveforms – Parallel Mode

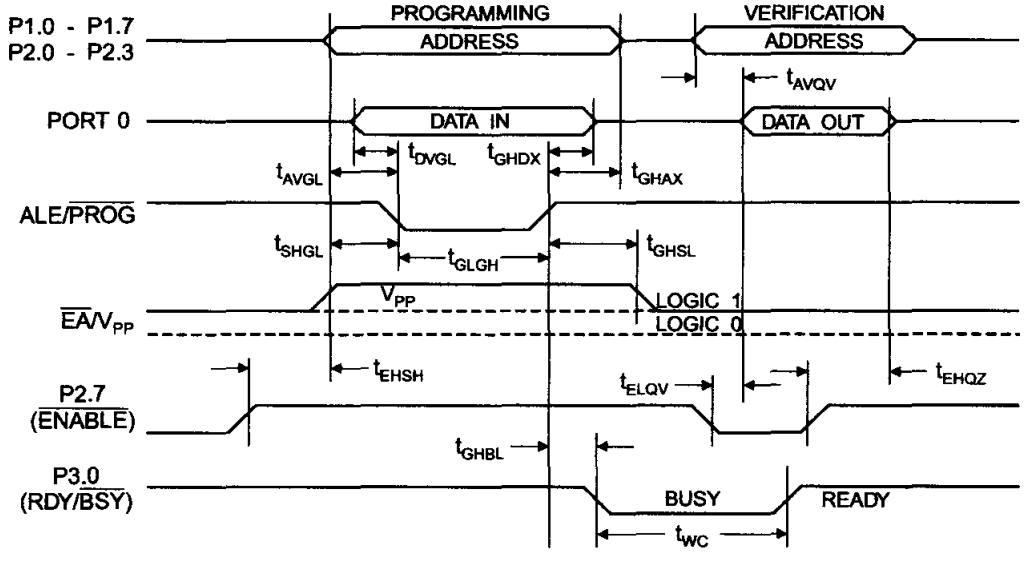
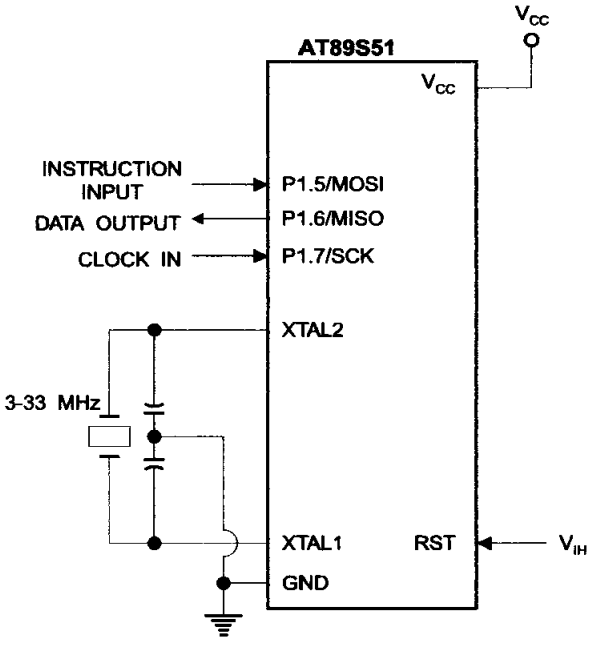


Figure 7. Flash Memory Serial Downloading



Flash Programming and Verification Waveforms – Serial Mode

Figure 8. Serial Programming Waveforms

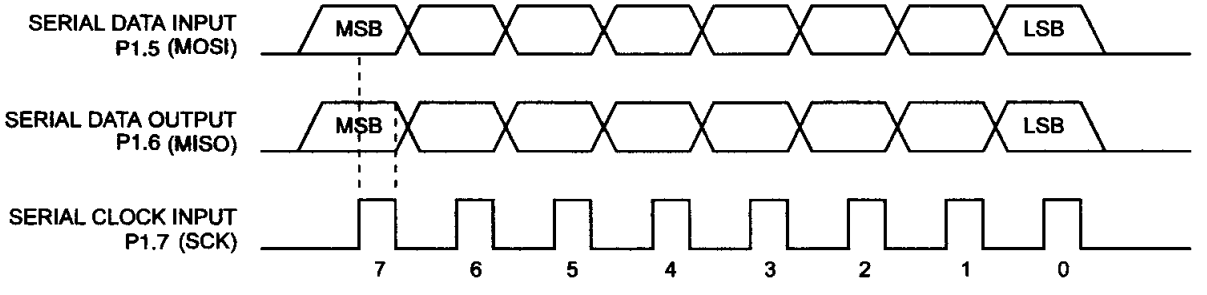


Table 8. Serial Programming Instruction Set

Instruction	Instruction Format Byte 1	Byte 2	Byte 3	Byte 4	Operation
Programming Enable	1010 1100	0101 0011	xxxx xxxx	xxxx xxxx 0110 1001 (Output on MISO)	Enable Serial Programming while RST is high
Chip Erase	1010 1100	100x xxxx	xxxx xxxx	xxxx xxxx	Chip Erase Flash memory array
Read Program Memory (Byte Mode)	0010 0000	xxxx A11 A10 A9 A8	A7 A6 A5 A4 A3 A2 A1 A0	D7 D6 D5 D4 D3 D2 D1 D0	Read data from Program memory in the byte mode
Write Program Memory (Byte Mode)	0100 0000	xxxx A11 A10 A9 A8	A7 A6 A5 A4 A3 A2 A1 A0	D7 D6 D5 D4 D3 D2 D1 D0	Write data to Program memory in the byte mode
Write Lock Bits[1]	1010 1100	1110 00 B1 B2	xxxx xxxx	xxxx xxxx	Write Lock bits. See Note (1).
Read Lock Bits	0010 0100	xxxx xxxx	xxxx xxxx	xxx LB3 LB2 LB1 xx	Read back current status of the lock bits (a programmed lock bit reads back as a "1")
Read Signature Bytes	0010 1000	xxxx A11 A10 A9 A8	A7 xxx xxx0	Signature Byte	Read Signature Byte
Read Program Memory (Page Mode)	0011 0000	xxxx A11 A10 A9 A8	Byte 0	Byte 1... Byte 255	Read data from Program memory in the Page Mode (256 bytes)
Write Program Memory (Page Mode)	0101 0000	xxxx A11 A10 A9 A8	Byte 0	Byte 1... Byte 255	Write data to Program memory in the Page Mode (256 bytes)

Note: 1. B1 = 0, B2 = 0 → Mode 1, no lock protection
B1 = 0, B2 = 1 → Mode 2, lock bit 1 activated
B1 = 1, B2 = 0 → Mode 3, lock bit 2 activated
B1 = 1, B2 = 1 → Mode 4, lock bit 3 activated

} Each of the lock bit modes need to be activated sequentially before Mode 4 can be executed.

After Reset signal is high, SCK should be low for at least 64 system clocks before it goes high to clock in the enable data bytes. No pulsing of Reset signal is necessary. SCK should be no faster than 1/16 of the system clock at XTAL1.

For Page Read/Write, the data always starts from byte 0 to 255. After the command byte and upper address byte are latched, each byte thereafter is treated as data until all 256 bytes are shifted in/out. Then the next instruction will be ready to be decoded.

Serial Programming Characteristics

Figure 9. Serial Programming Timing

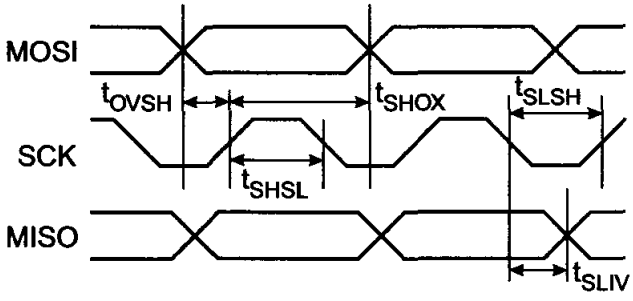


Table 9. Serial Programming Characteristics, T_A = -40° C to 85° C, V_{CC} = 4.0 - 5.5V (Unless Otherwise Noted)

Symbol	Parameter	Min	Typ	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	3		33	MHz
t_{CLCL}	Oscillator Period	30			ns
t_{SHSL}	SCK Pulse Width High	8 t_{CLCL}			ns
t_{SLSH}	SCK Pulse Width Low	8 t_{CLCL}			ns
t_{OVSH}	MOSI Setup to SCK High	t_{CLCL}			ns
t_{SHOX}	MOSI Hold after SCK High	2 t_{CLCL}			ns
t_{SLIV}	SCK Low to MISO Valid	10	16	32	ns
t_{ERASE}	Chip Erase Instruction Cycle Time			500	ms
t_{SWC}	Serial Byte Write Cycle Time			64 t_{CLCL} + 400	µs

Absolute Maximum Ratings*

Operating Temperature	-55°C to +125°C
Storage Temperature	-65°C to +150°C
Voltage on Any Pin with Respect to Ground	-1.0V to +7.0V
Maximum Operating Voltage	6.6V
DC Output Current	15.0 mA

*NOTICE: Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

DC Characteristics

The values shown in this table are valid for T_A = -40°C to 85°C and V_{CC} = 4.0V to 5.5V, unless otherwise noted.

Symbol	Parameter	Condition	Min	Max	Units
V_{IL}	Input Low Voltage	(Except $\overline{EA}$)	-0.5	0.2 V_{CC}-0.1	V
V_{IL1}	Input Low Voltage ($\overline{EA}$)		-0.5	0.2 V_{CC}-0.3	V
V_{IH}	Input High Voltage	(Except XTAL1, RST)	0.2 V_{CC}+0.9	V_{CC}+0.5	V
V_{IH1}	Input High Voltage	(XTAL1, RST)	0.7 V_{CC}	V_{CC}+0.5	V
V_{OL}	Output Low Voltage[1] (Ports 1,2,3)	I_{OL} = 1.6 mA		0.45	V
V_{OL1}	Output Low Voltage[1] (Port 0, ALE, $\overline{PSEN}$)	I_{OL} = 3.2 mA		0.45	V
V_{OH}	Output High Voltage (Ports 1,2,3, ALE, $\overline{PSEN}$)	I_{OH} = -60 µA, V_{CC} = 5V ±10%	2.4		V
		I_{OH} = -25 µA	0.75 V_{CC}		V
		I_{OH} = -10 µA	0.9 V_{CC}		V
V_{OH1}	Output High Voltage (Port 0 in External Bus Mode)	I_{OH} = -800 µA, V_{CC} = 5V ±10%	2.4		V
		I_{OH} = -300 µA	0.75 V_{CC}		V
		I_{OH} = -80 µA	0.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1,2,3)	V_{IN} = 0.45V		-50	µA
I_{TL}	Logical 1 to 0 Transition Current (Ports 1,2,3)	V_{IN} = 2V, V_{CC} = 5V ±10%		-650	µA
I_{LI}	Input Leakage Current (Port 0, $\overline{EA}$)	0.45 < V_{IN} < V_{CC}		±10	µA
RRST	Reset Pulldown Resistor		50	300	KΩ
C_{IO}	Pin Capacitance	Test Freq. = 1 MHz, T_A = 25°C		10	pF
I_{CC}	Power Supply Current	Active Mode, 12 MHz		25	mA
		Idle Mode, 12 MHz		6.5	mA
	Power-down Mode[2]	V_{CC} = 5.5V		50	µA

Notes:
1. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:
   Port 0: 26 mA Ports 1, 2, 3: 15 mA
   Maximum total I_{OL} for all output pins: 71 mA
   If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
2. Minimum V_{CC} for Power-down is 2V.

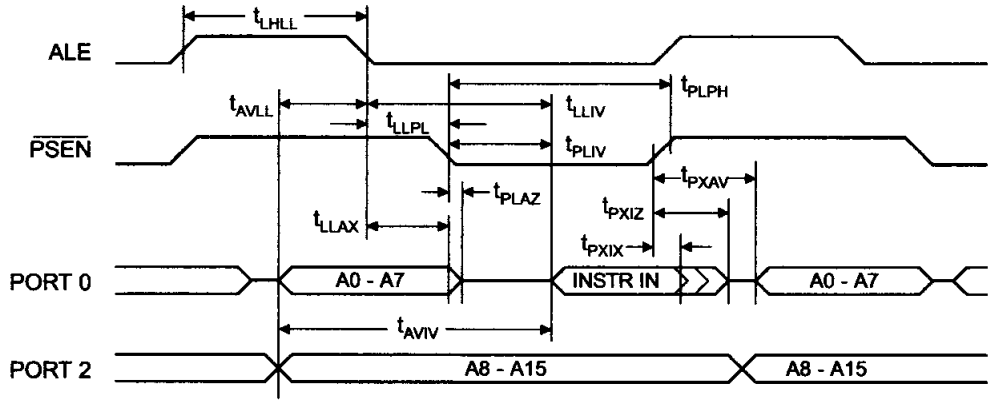
AC Characteristics

Under operating conditions, load capacitance for Port 0, ALE/$\overline{PROG}$, and $\overline{PSEN}$ = 100 pF; load capacitance for all other outputs = 80 pF.

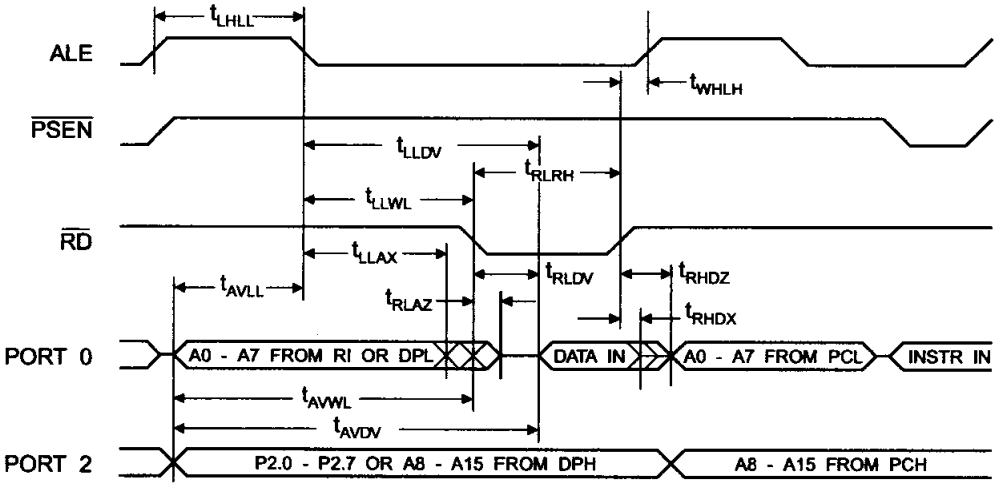
External Program and Data Memory Characteristics

Symbol	Parameter	12 MHz Oscillator		Variable Oscillator		Units
		Min	Max	Min	Max	
$1/t_{CLCL}$	Oscillator Frequency			0	33	MHz
t_{LHLL}	ALE Pulse Width	127		$2t_{CLCL}$-40		ns
t_{AVLL}	Address Valid to ALE Low	43		t_{CLCL}-25		ns
t_{LLAX}	Address Hold After ALE Low	48		t_{CLCL}-25		ns
t_{LLIV}	ALE Low to Valid Instruction In		233		$4t_{CLCL}$-65	ns
t_{LLPL}	ALE Low to $\overline{PSEN}$ Low	43		t_{CLCL}-25		ns
t_{PLPH}	$\overline{PSEN}$ Pulse Width	205		$3t_{CLCL}$-45		ns
t_{PLIV}	$\overline{PSEN}$ Low to Valid Instruction In		145		$3t_{CLCL}$-60	ns
t_{PXIX}	Input Instruction Hold After $\overline{PSEN}$	0		0		ns
t_{PXIZ}	Input Instruction Float After $\overline{PSEN}$		59		t_{CLCL}-25	ns
t_{PXAV}	$\overline{PSEN}$ to Address Valid	75		t_{CLCL}-8		ns
t_{AVIV}	Address to Valid Instruction In		312		$5t_{CLCL}$-80	ns
t_{PLAZ}	$\overline{PSEN}$ Low to Address Float		10		10	ns
t_{RLRH}	$\overline{RD}$ Pulse Width	400		$6t_{CLCL}$-100		ns
t_{WLWH}	$\overline{WR}$ Pulse Width	400		$6t_{CLCL}$-100		ns
t_{RLDV}	$\overline{RD}$ Low to Valid Data In		252		$5t_{CLCL}$-90	ns
t_{RHDX}	Data Hold After $\overline{RD}$	0		0		ns
t_{RHDZ}	Data Float After $\overline{RD}$		97		$2t_{CLCL}$-28	ns
t_{LLDV}	ALE Low to Valid Data In		517		$8t_{CLCL}$-150	ns
t_{AVDV}	Address to Valid Data In		585		$9t_{CLCL}$-165	ns
t_{LLWL}	ALE Low to $\overline{RD}$ or $\overline{WR}$ Low	200	300	$3t_{CLCL}$-50	$3t_{CLCL}$+50	ns
t_{AVWL}	Address to $\overline{RD}$ or $\overline{WR}$ Low	203		$4t_{CLCL}$-75		ns
t_{QVWX}	Data Valid to $\overline{WR}$ Transition	23		t_{CLCL}-30		ns
t_{QVWH}	Data Valid to $\overline{WR}$ High	433		$7t_{CLCL}$-130		ns
t_{WHQX}	Data Hold After $\overline{WR}$	33		t_{CLCL}-25		ns
t_{RLAZ}	$\overline{RD}$ Low to Address Float		0		0	ns
t_{WHLH}	$\overline{RD}$ or $\overline{WR}$ High to ALE High	43	123	t_{CLCL}-25	t_{CLCL}+25	ns

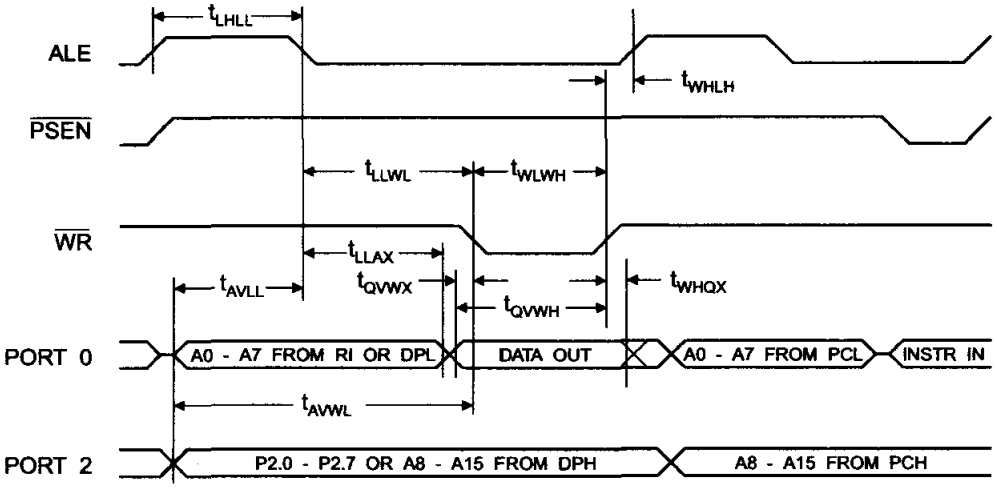
External Program Memory Read Cycle



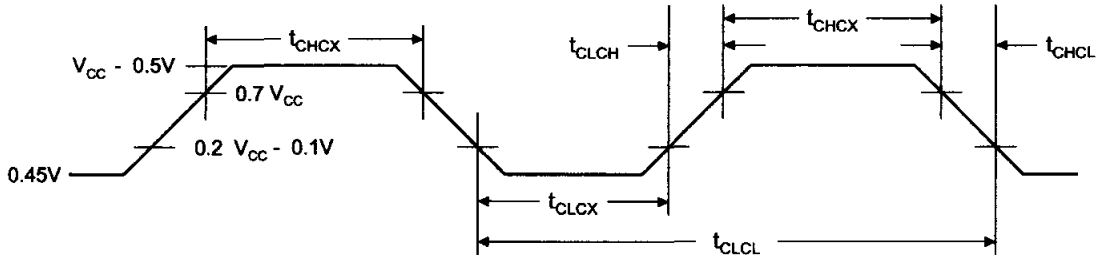
External Data Memory Read Cycle



External Data Memory Write Cycle



External Clock Drive Waveforms



External Clock Drive

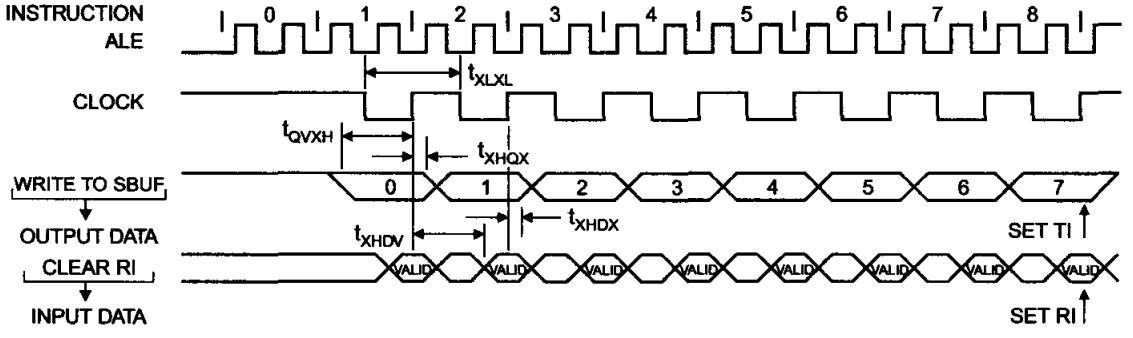
Symbol	Parameter	Min	Max	Units
$1/t_{CLCL}$	Oscillator Frequency	0	33	MHz
t_{CLCL}	Clock Period	30		ns
t_{CHCX}	High Time	12		ns
t_{CLCX}	Low Time	12		ns
t_{CLCH}	Rise Time		5	ns
t_{CHCL}	Fall Time		5	ns

Serial Port Timing: Shift Register Mode Test Conditions

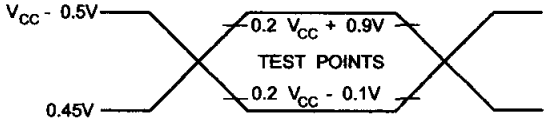
The values in this table are valid for V_{CC} = 4.0V to 5.5V and Load Capacitance = 80 pF.

Symbol	Parameter	12 MHz Osc		Variable Oscillator		Units
		Min	Max	Min	Max	
t_{XLXL}	Serial Port Clock Cycle Time	1.0		$12t_{CLCL}$		µs
t_{QVXH}	Output Data Setup to Clock Rising Edge	700		$10t_{CLCL}$-133		ns
t_{XHQX}	Output Data Hold After Clock Rising Edge	50		$2t_{CLCL}$-80		ns
t_{XHDX}	Input Data Hold After Clock Rising Edge	0		0		ns
t_{XHDV}	Clock Rising Edge to Input Data Valid		700		$10t_{CLCL}$-133	ns

Shift Register Mode Timing Waveforms

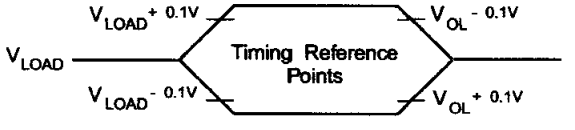


AC Testing Input/Output Waveforms[1]



Note: 1. AC Inputs during testing are driven at V_{CC} - 0.5V for a logic 1 and 0.45V for a logic 0. Timing measurements are made at V_{IH} min. for a logic 1 and V_{IL} max. for a logic 0.

Float Waveforms[1]



Note: 1. For timing purposes, a port pin is no longer floating when a 100 mV change from load voltage occurs. A port pin begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs.

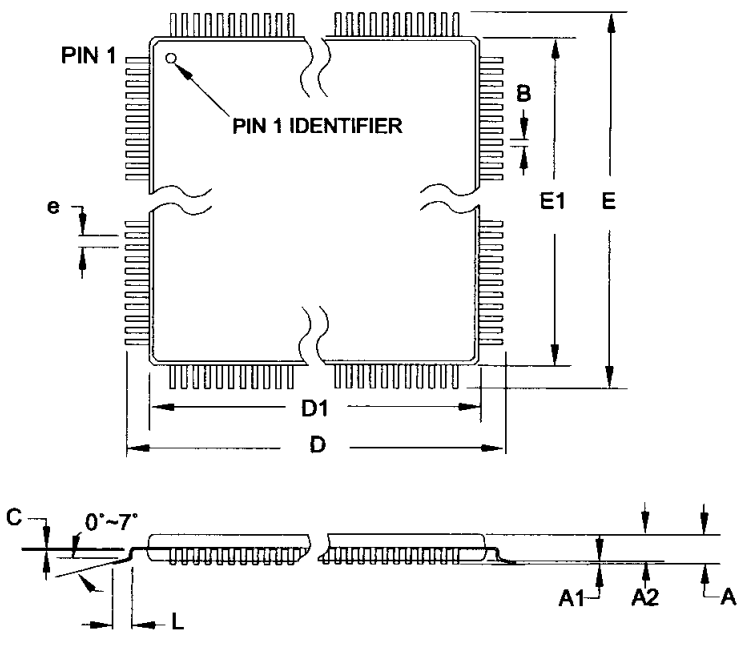
Ordering Information

Speed (MHz)	Power Supply	Ordering Code	Package	Operation Range
24	4.0V to 5.5V	AT89S51-24AC AT89S51-24JC AT89S51-24PC AT89S51-24SC	44A 44J 40P6 42PS6	Commercial (0° C to 70° C)
		AT89S51-24AI AT89S51-24JI AT89S51-24PI AT89S51-24SI	44A 44J 40P6 42PS6	Industrial (-40° C to 85° C)
33	4.5V to 5.5V	AT89S51-33AC AT89S51-33JC AT89S51-33PC AT89S51-33SC	44A 44J 40P6 42PS6	Commercial (0° C to 70° C)

Package Type	
44A	44-lead, Thin Plastic Gull Wing Quad Flatpack (TQFP)
44J	44-lead, Plastic J-leaded Chip Carrier (PLCC)
40P6	40-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)
42PS6	42-pin, 0.600" Wide, Plastic Dual Inline Package (PDIP)

Packaging Information

44A – TQFP



COMMON DIMENSIONS
(Unit of Measure = mm)

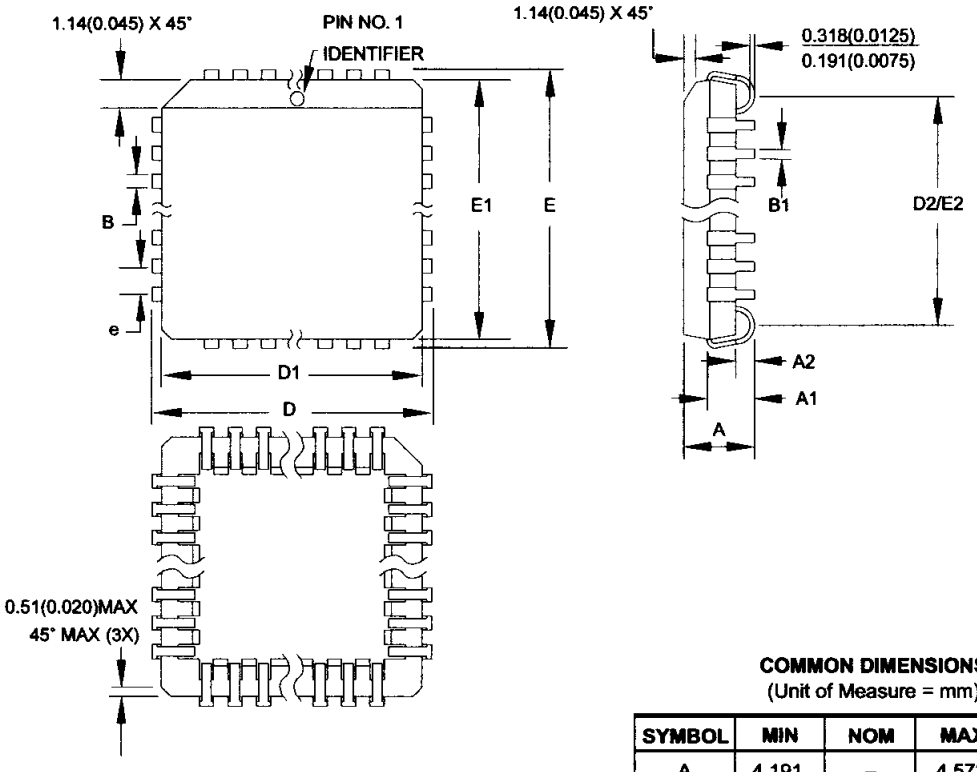
SYMBOL	MIN	NOM	MAX	NOTE
A	–	–	1.20	
A1	0.05	–	0.15	
A2	0.95	1.00	1.05	
D	11.75	12.00	12.25	
D1	9.90	10.00	10.10	Note 2
E	11.75	12.00	12.25	
E1	9.90	10.00	10.10	Note 2
B	0.30	–	0.45	
C	0.09	–	0.20	
L	0.45	–	0.75	
e	0.80 TYP			

Notes:
1. This package conforms to JEDEC reference MS-026, Variation ACB.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25 mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10 mm maximum.

10/5/2001

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44A,** 44-lead, 10 x 10 mm Body Size, 1.0 mm Body Thickness, 0.8 mm Lead Pitch, Thin Profile Plastic Quad Flat Package (TQFP)	44A	B

44J – PLCC



COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	4.191	–	4.572	
A1	2.286	–	3.048	
A2	0.508	–	–	
D	17.399	–	17.653	
D1	16.510	–	16.662	Note 2
E	17.399	–	17.653	
E1	16.510	–	16.662	Note 2
D2/E2	14.986	–	16.002	
B	0.660	–	0.813	
B1	0.330	–	0.533	
e	1.270 TYP			

Notes:
1. This package conforms to JEDEC reference MS-018, Variation AC.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is .010"(0.254 mm) per side. Dimension D1 and E1 include mold mismatch and are measured at the extreme material condition at the upper or lower parting line.
3. Lead coplanarity is 0.004" (0.102 mm) maximum.

10/04/01

	TITLE	DRAWING NO.	REV.
2325 Orchard Parkway San Jose, CA 95131	**44J**, 44-lead, Plastic J-leaded Chip Carrier (PLCC)	44J	B

Atmel Corporation

2325 Orchard Parkway
San Jose, CA 95131, USA
Tel: 1(408) 441-0311
Fax: 1(408) 487-2600

Regional Headquarters

Europe
Atmel Sarl
Route des Arsenaux 41
Case Postale 80
CH-1705 Fribourg
Switzerland
Tel: (41) 26-426-5555
Fax: (41) 26-426-5500

Asia
Room 1219
Chinachem Golden Plaza
77 Mody Road Tsimshatsui
East Kowloon
Hong Kong
Tel: (852) 2721-9778
Fax: (852) 2722-1369

Japan
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
Japan
Tel: (81) 3-3523-3551
Fax: (81) 3-3523-7581

Atmel Operations

Memory
2325 Orchard Parkway
San Jose, CA 95131, USA
Tel: 1(408) 441-0311
Fax: 1(408) 436-4314

Microcontrollers
2325 Orchard Parkway
San Jose, CA 95131, USA
Tel: 1(408) 441-0311
Fax: 1(408) 436-4314

La Chantrerie
BP 70602
44306 Nantes Cedex 3, France
Tel: (33) 2-40-18-18-18
Fax: (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards
Zone Industrielle
13106 Rousset Cedex, France
Tel: (33) 4-42-53-60-00
Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906, USA
Tel: 1(719) 576-3300
Fax: 1(719) 540-1759

Scottish Enterprise Technology Park
Maxwell Building
East Kilbride G75 0QR, Scotland
Tel: (44) 1355-803-000
Fax: (44) 1355-242-743

RF/Automotive
Theresienstrasse 2
Postfach 3535
74025 Heilbronn, Germany
Tel: (49) 71-31-67-0
Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906, USA
Tel: 1(719) 576-3300
Fax: 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/
High Speed Converters/RF Datacom
Avenue de Rochepleine
BP 123
38521 Saint-Egreve Cedex, France
Tel: (33) 4-76-58-30-00
Fax: (33) 4-76-58-34-80

Literature Requests
www.atmel.com/literature

2487B–MICRO–12/03